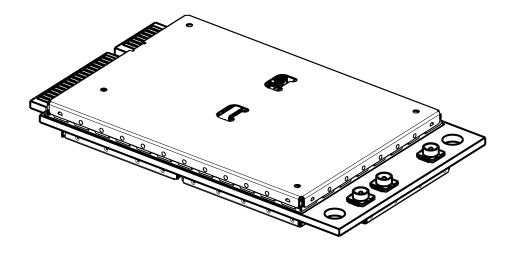


Product Technical Specification & Customer Design Guidelines

AirPrime MC7750





2400074 Rev 4 Distribution under NDA only Contents subject to change

Important Notice

Due to the nature of wireless communications, transmission and reception of data can never be guaranteed. Data may be delayed, corrupted (i.e., have errors) or be totally lost. Although significant delays or losses of data are rare when wireless devices such as the Sierra Wireless modem are used in a normal manner with a well-constructed network, the Sierra Wireless modem should not be used in situations where failure to transmit or receive data could result in damage of any kind to the user or any other party, including but not limited to personal injury, death, or loss of property. Sierra Wireless accepts no responsibility for damages of any kind resulting from delays or errors in data transmitted or received using the Sierra Wireless modem, or for failure of the Sierra Wireless modem to transmit or receive such data.

Safety and Hazards

Do not operate the Sierra Wireless modem in areas where blasting is in progress, where explosive atmospheres may be present, near medical equipment, near life support equipment, or any equipment which may be susceptible to any form of radio interference. In such areas, the Sierra Wireless modem **MUST BE POWERED OFF.** The Sierra Wireless modem can transmit signals that could interfere with this equipment.

Do not operate the Sierra Wireless modem in any aircraft, whether the aircraft is on the ground or in flight. In aircraft, the Sierra Wireless modem **MUST BE POWERED OFF.** When operating, the Sierra Wireless modem can transmit signals that could interfere with various onboard systems.

Note: Some airlines may permit the use of cellular phones while the aircraft is on the ground and the door is open. Sierra Wireless modems may be used at this time.

The driver or operator of any vehicle should not operate the Sierra Wireless modem while in control of a vehicle. Doing so will detract from the driver or operator's control and operation of that vehicle. In some states and provinces, operating such communications devices while in control of a vehicle is an offence.

Limitation of Liability

The information in this manual is subject to change without notice and does not represent a commitment on the part of Sierra Wireless. SIERRA WIRELESS AND ITS AFFILIATES SPECIFICALLY DISCLAIM LIABILITY FOR ANY AND ALL DIRECT, INDIRECT, SPECIAL, GENERAL, INCIDENTAL, CONSEQUENTIAL, PUNITIVE OR EXEMPLARY DAMAGES INCLUDING, BUT NOT LIMITED TO, LOSS OF PROFITS OR REVENUE OR ANTICIPATED PROFITS OR REVENUE ARISING OUT OF THE USE OR INABILITY TO USE ANY SIERRA WIRELESS PRODUCT, EVEN IF SIERRA WIRELESS AND/OR ITS AFFILIATES HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES OR THEY ARE FORESEEABLE OR FOR CLAIMS BY ANY THIRD PARTY.

Notwithstanding the foregoing, in no event shall Sierra Wireless and/or its affiliates aggregate liability arising under or in connection with the Sierra Wireless product, regardless of the number of events, occurrences, or claims giving rise to liability, be in excess of the price paid by the purchaser for the Sierra Wireless product.

Patents

This product may contain technology developed by or for Sierra Wireless Inc.

This product includes technology licensed from QUALCOMM® 3G.

This product is manufactured or sold by Sierra Wireless Inc. or its affiliates under one or more patents licensed from InterDigital Group.

Copyright

©2011 Sierra Wireless. All rights reserved.

Trademarks

AirCard[®] and Watcher[™] are registered trademarks of Sierra Wireless. Sierra Wireless[™], AirPrime[™] and the Sierra Wireless logo are trademarks of Sierra Wireless.

Windows[®] and Windows Vista[®] are registered trademarks of Microsoft Corporation.

Macintosh and Mac OS X are registered trademarks of Apple Inc., registered in the U.S. and other countries.

QUALCOMM® is a registered trademark of QUALCOMM Incorporated. Used under license.

Other trademarks are the property of their respective owners.

Contact Information

Sales Desk:	Phone:	1-604-232-1488
	Hours:	8:00 AM to 5:00 PM Pacific Time
	E-mail:	sales@sierrawireless.com
Post:	Sierra Wireless 13811 Wireless Way Richmond, BC Canada V6V 3A4	
Fax:	1-604-231-1109	
Web:	www.sierrawireless.com	

Consult our website for up-to-date product descriptions, documentation, application notes, firmware upgrades, troubleshooting tips, and press releases:

www.sierrawireless.com

Revision History

Revision number	Release date	Changes
1	August 2010	Initial release.
2	January 2011	Resolved most TBDs.
		Removed references to dial-up networking.
		Updated Figure 4-1, System block diagram, on page 24; Figure 4-2, Expanded RF block diagram, on page 25; Figure 8-2, Dimensioned view, on page 54.
		Updated Table 5-5, Conducted Rx (Receive) sensitivity, on page 43; Table 6-1, Averaged standby DC power consumption, on page 45; Table 6-3, Averaged call mode DC power consumption (LTE), on page 46; Table 6-4, Averaged Call Mode DC power consumption (GSM/EDGE), on page 70.
		Added a list of tables and list of figures.
		Removed unused glossary entries.
3	May 2011	General review and redraft
4	September 2011	Updated LED table
		Removed UMTS/GSM references
		Updated LTE power consumption
		Added suggested antenna part number



Introduction	15
Supported RF bands	15
Physical features	15
Application interface features	15
Packet mode features	16
LTE features	16
Short Message Service (SMS) features	16
Position location (GPS)	17
Warranty and support	17
Supporting documents	17
Accessories	17
Required connectors	18
Ordering information	18
Integration requirements	18
Technology Overview	19
LTE	19
CDMA	19
1xEV-DO	
1X and IS-95A	20
Standards Compliance	21
Electrical Specifications	23
Host interface pin assignments	25
Power supply	29
USB interface	29
USB high/full speed throughput performance	
User-developed drivers	30

SIM interface	30
SIM implementation	32
Control interface (Signals)	33
W_DISABLE_N — Wireless disable	33
WLAN_LED_N—LED output	34
Digital interface	35
RF Specifications	37
RF connections	37
Shielding	37
Antenna and cabling	38
Ground connection	39
Interference and sensitivity	39
Interference from other wireless devices	39
Host-generated RF interference	40
Device-generated RF interference	40
Methods to mitigate decreased Rx performance	40
Radiated Spurious Emissions (RSE)	40
Radiated sensitivity measurement	41
Sierra Wireless' sensitivity testing and desensitization investigation	41
Sensitivity vs. frequency	41
Supported frequencies	41
Conducted Rx sensitivity / Tx power	42
GPS specifications	43
Power	45
Power consumption	45
	47
Power state transitions	1 2

Power interface	49
Power ramp-up	49
Power-up timing	49
Power supply noise	50
SED (Smart Error Detection)	50
Ooftware leterfore	F.4
Software Interface	
Support tools	51
USB interface	51
TCP window size (Windows XP)	51
Mechanical and Environmental Specifications	53
Device views	
Labeling	
Electrostatic discharge (ESD)	
Thermal considerations	56
Regulatory and Industry Approvals	59
Important notice	59
Safety and hazards	59
Important compliance information for North American users	60
OEM integration	
Application of regulatory guidelines	
OEM device classification process	
OZINI dovido diadomodilon prodoco	
Antenna Specification	65
Recommended GPS antenna specifications	67
Antenna tests	
Design Checklist	69
Testing	71
AT command entry timing requirement	71

Acceptance testing
Acceptance test requirements
Acceptance test procedure
Certification testing
Production testing
Functional production test
Production test procedure
Testing CDMA RF Receive path
LTE RF receive path test
GPS standalone connector test
Quality assurance testing 80
Suggested testing equipment
Testing assistance provided by Sierra Wireless 81
IOT/Operator testing
Extended AT commands for testing
Deal action
Packaging85
References
Web site support
Sierra Wireless documents
Command documents
Other Sierra documents
Industry/other documents
Acronyms89



Table 1-1: Supported RF bands
Table 1-2: Required host-module connectors
Table 3-1: Standards compliance
Table 4-1: Connector pin assignments
Table 4-2: Power and ground specifications
Table 4-3: USB interface
Table 4-4: SIM interface signal
Table 4-5: Module control signals
Table 4-6: LED states (Default behavior) 34
Table 4-7: GPIO signals
Table 5-1: LTE frequency band support
Table 5-2: LTE bandwidth support
Table 5-3: CDMA frequency band support
Table 5-4: Conducted Rx (Receive) sensitivity—LTE bands
Table 5-5: Conducted Rx (Receive) sensitivity—CDMA bands 42
Table 5-6: Conducted Tx (Transmit) power tolerances
Table 5-7: GPS specifications
Table 6-1: Averaged standby DC power consumption
Table 6-2: CDMA DC power consumption (+3.3V)
Table 6-3: Averaged call mode DC power consumption (LTE)
Table 6-4: Miscellaneous DC power consumption 47
Table 6-5: Module power states
Table 6-6: Power state transitions (including voltage/temperature trigger levels) 48
Table 8-1: Mechanical and environmental specifications 53
Table A-1: Antenna requirements
Table A-2: GPS standalone antenna requirements 67
Table B-1: Hardware integration design considerations 69

Product Technical Specification & Customer Design Guidelines

Table C-1: Test settings—Receive path	78
Table C-2: Extended AT commands	82
Table F-1: Acronyms and definitions	89



Figure 4-1: System block diagram	24
Figure 4-2: Expanded RF block diagram	25
Figure 4-3: SIM application interface 3	31
Figure 4-4: SIM card contacts (contact view)	31
Figure 4-5: Recommended wireless disable connection	33
Figure 4-6: Example LED 3	34
Figure 5-1: Module connectors	37
Figure 6-1: Voltage/temperature monitoring state machines	19
Figure 6-2: Power-up timing diagram4	19
Figure 8-1: Top and bottom views	54
Figure 8-2: Dimensioned view	54
Figure 8-3: Unit label	55
Figure 8-4: Shield locations	56
Figure 4-1: Device placement in module tray	35
Figure 4-2: Shipping package	35

>> 1: Introduction

The Sierra Wireless MC7750 PCI Express Mini Card is a compact, lightweight, wireless LTE- and CDMA-based modem, designed to be Verizon Wireless certified.

The MC7750 provides LTE, CDMA, and GPS connectivity for portable and handheld computers, point-of-sale devices, telemetry products and other machine-to-machine and vertical applications over several radio frequency bands.

Supported RF bands

The modem, based on Qualcomm's MDM9600 baseband processor, supports data operation on LTE and CDMA networks.

Table 1-1: Supported RF bands

Technology	Bands	Diversity
LTE	• Band 13: 700 MHz	(MIMO)
CDMA	Cellular (800 MHz)PCS (1900 MHz)	✓
GPS	• 1575.42 MHz	n/a

Physical features

- Small form factor—conforms to F1 as specified in *PCI Express Mini Card Electromechanical Specification Revision 1.2*.
- Operating temperature range: -30 °C to +60 °C

Application interface features

- USB interface (QMI)
- NDIS NIC interface support for Windows 7, Windows Vista, and Windows XP platforms
- Multiple non-multiplexed USB channel support
- USB selective suspend to maximize power savings
- AT command interface ([1] AT Command Set for User Equipment (UE) (Release 6) (Doc# 3GPP TS 27.007), plus proprietary extended AT commands)
- Software Development Kit (SDK) including a Linux API (Application Program Interface)

 WMC DLL support for Verizon Wireless PC-OEM (Windows)OMA DM (Open Mobile Alliance Device Management)FOTA (Firmware Over The Air)

Packet mode features

- LTE data rates (category 3, MIMO)
 - · 100 Mbps DL within 20 MHz bandwidth
 - 50 Mbps UL within 20 MHz bandwidth
- CDMA IS-856 (1xEV-DO Rev. A) data rates
 - · Up to 3.1 Mbps forward channel
 - Up to 1.8 Mbps reverse channel
- CDMA IS-2000 data rates—Up to 153 kbps, simultaneous forward and reverse channel
- Circuit-switched data bearers (up to 14.4 for CDMA)

LTE features

- Basic cell selection and system acquisition
 - PSS/SSS/MIB decode
 - SIB1, SIB2, SIB3 decoding
- NAS/AS security procedures
 - Snow 3G/AES security
- CQI/RI reporting
- Paging procedures
 - · Paging in Idle and Connected mode
- Dedicated bearer
 - · Network-initiated dedicated bearer
 - UE-initiated dedicated bearer
- Multiple PDN connections (IPv4 and IPv6 combinations)
- Connected mode intra-LTE mobility
- Idle mode intra-LTE mobility
- iRAT between LTE/2G (future release)
 iRAT between LTE/3G for idle and connection release with redirection (future release)
- Detach procedure
 - · Network-initiated detach with reattach required
 - · Network-initiated detach followed by connection release
- LTE → eHRPD redirection with data continuity (IPv4/IPv6)

Short Message Service (SMS) features

- Mobile-terminated SMS for CDMA
- Mobile-originated SMS for CDMA
- Mobile-terminated SMS over IMS for LTE/eHRPD

Mobile-originated SMS over IMS for LTE/eHRPD

Position location (GPS)

- Standalone mode
- GLONASS support on GPS connector 1 (future release)
- DC bias on GPS connector 1 to support external active GPS antenna

Warranty and support

The MC7750 offers the following support features:

- Standard 1-year warranty
- Enabling software (drivers, SDK, etc.) for Android, Linux, Windows 7, Windows Vista, and Windows XP

Supporting documents

Several additional documents describe Mini Card design, usage, integration, and other features. See References on page 87.

Accessories

The Universal Development Kit (UDK) is a hardware development platform for AirPrime MC-series modules. It contains hardware components for evaluating and developing with the module, including:

- Development board
- Cables
- Antennas (Bands 17, 13, and 7 are not supported by supplied antennas)
- Documentation suite
- Initial allotment of support hours
- Other accessories

For instructions on setting up the UDK, see [4] PCI Express Mini Card Dev Kit Quick Start Guide (Doc# 2130705).

For over-the-air LTE testing, ensure that suitable antennas are used. (Two antennas are required for this testing; Sierra Wireless offers an LTE-capable antenna covering 700–2600 MHz BW—please order part number 6000492 (Qty 1—this contains two antennas).)

Required connectors

Table 1-2 describes the connectors used to integrate AirPrime MC-series modules into your host device.

Table 1-2: Required host-module connectors¹

Connector type	Description
RF cables	Mate with Hirose U.FL connectors (model U.FL #CL331-0471-0-10)
	 Two or three connector jacks, depending on module support for diversity and GPS functionality. (Note: The UDK has two connector jacks.)
EDGE (52-pin)	Industry-standard mating connector
	Some manufacturers include Tyco, Foxconn, Molex
	Example: UDK board uses Molex 67910-0001
SIM	Industry-standard connector. Type depends on how host device exposes the SIM socket
	Example: UDK board uses ITT CCM03-3518

^{1.} Manufacturers/part numbers are for reference only and are subject to change. Choose connectors that are appropriate for your own design.

Ordering information

To order, contact the Sierra Wireless Sales Desk at +1 (604) 232-1488 between 8 AM and 5 PM Pacific Time.

Integration requirements

Sierra Wireless provides, in the document suite, guidelines for successful Mini Card integration and offers integration support services as necessary.

When integrating the MC7750 PCI-Express Mini Card, the following items need to be addressed:

- Mounting—Effect on temperature, shock, and vibration performance
- Power supply—Impact on battery drain and possible RF interference
- Antenna location and type—Impact on RF performance
- Regulatory approvals—As discussed in Regulatory and Industry Approvals on page 59.
- Service provisioning—Manufacturing process
- Software—As discussed in Software Interface on page 51.
- Host Interface, compliance with interface voltage levels

>> 2: Technology Overview

LTE

LTE (Long Term Evolution) is a 4th-generation wireless standard. The 3GPP Release 8 specification outlines the features and requirements.

Key features include.

- Peak data rate:
 - 100 Mbps DL within 20 MHz bandwidth
 (Peak DL data rate in 10 MHz bandwidth: 70 Mbps (approx.) for
 Cat 3 device)
 - 50 Mbps UL within 20 MHz bandwidth

Actual throughput is dependent on the network configuration, bandwidth assigned to the UE, the number of users, and RF signal conditions.

- Up to 200 active users in a cell (5 MHz)
- Less than 5 ms user-plane latency
- Supported bandwidths: 5 MHz/10 MHz
- Spectrum flexibility: 1.4–20 MHz (3–20 MHz in future F/W release)
- Enhanced support for end-to-end QOS
- Physical layer uses:
 - DL: OFDMA (Orthogonal Frequency Division Multiple Access).
 Modulation: QPSK, 16QAM, and 64QAM
 - UL: Single Carrier FDMA (single carrier modulation and orthogonal frequency multiplexing)
 Modulation: QPSK, 16QAM
- MIMO (Multi-Input Multi-Output) antenna support

CDMA

1xEV-DO

1xEV-DO is backwards compatible to both 1X and IS-95A/B standards. However, 1xEV-DO represents an evolutionary enhancement, specifically designed and optimized for high-speed wireless data access. This was driven by fundamental differences between voice and data traffic characteristics.

eHRPD (Enhanced High Rate Packet Data) is an enhancement of 1xEV-DO that enables LTE to CDMA handover.

To optimize for data, there are some fundamental characteristics and differences between 1X and 1xEV-DO, including:

- The network has dedicated spectrum (1.25 MHz) for data traffic using 1xEV-DO standard, so resources don't compete with 1X data/voice (hybrid mode used to monitor 1X carriers)
- BTS always transmits at maximum available power
- Each user receives data from only one base station at a time (no forward link soft handoff)
- 1xEV-DO lets each user use 100% of available resources, while dynamically allocating time resources among users for maximum efficiency
- 1xEV-DO uses time-division multiplexing of users on forward link (slots assigned for packet transmission)
- Forward link supports higher order modulation (QPSK, 8-PSK and 16-QAM)
- Reverse link (1xEV-DO Revision A) supports higher order modulation (8-PSK)
- Mobile supports dynamic channel estimation using measured S/N to set the highest rate it can decode (uses Data Rate Control channel to communicate to network access point)
- Mobiles can support Rx diversity for S/N enhancements particularly in multipath/fading environments

1X and IS-95A

The type of data connection made at any given time depends on the services available from the carrier in the given coverage area. If 1X packet services are not available, the modem connects using circuit-switched data over IS-95A technology. The modem automatically selects the fastest connection mode available when a data call is connecting.

When roaming, the modem **does not** automatically change connection modes. If the modem connects using 1X and then roams outside of the packet service area, the connection is dropped. To resume data communication, a new connection using IS-95A has to be created. Similarly, an IS-95A call established in one area does not automatically transition to 1X when the unit enters the 3G coverage area.

>>> 3: Standards Compliance

The MC7750 Mini Card complies with the mandatory requirements described in the following standards. The exact set of requirements supported is carrier-dependent.

Table 3-1: Standards compliance

Technology	Standards
LTE	3GPP Release 8
CDMA	TIA/EIA/IS-2000.1 through .6. cdma2000® Standards for Spread Spectrum Systems. Release 0. April 2000
	• TIA/EIA/IS-2000.1-1 through .6-1. cdma2000® Addendum 1. April 2000
	• TIA/EIA/IS-2000.1-2 through .6-2. cdma2000® Addendum 2. June 2001
	TIA/EIA/IS-95-B. Mobile Station-Base Station Compatibility Standard for Dual-Mode Spread Spectrum Systems. December 4, 1998
	TIA/EIA/IS cdma2000® High Rate Packet Data Air Interface Specification. November 2000

>> 4: Electrical Specifications

The system block diagram in Figure 4-1 represents the MC7750 module integrated into a host system. The module includes the following interfaces to the host:

- Power—Supplied to the module by the host.
- W_DISABLE_N—Active low input from a hardware switch to the MC7750 that disables the main RF radio.
- WLAN_LED_N—Active-low LED drive signal provides an indication of RADIO ON state, either WAN or GPS.
- Antenna—Three U.FL RF connectors (two for Rx/Tx, and one for GPS). For details, see RF Specifications on page 37.
 Note that GPS can use either the dedicated GPS port, or the diversity/MIMO port. GLONASS is supported only on the dedicated GPS port.
- SIM—Supported through the interface connector. The SIM cavity / connector must be placed on the host device for this feature.
- USB—Interface to the host for data, control, and status information.
- GPIO—Six GPIOs reserved for future use.

The MC7750 has two main interface areas—the host I/O connector and the RF ports. Details of these interfaces are described in the sections that follow.

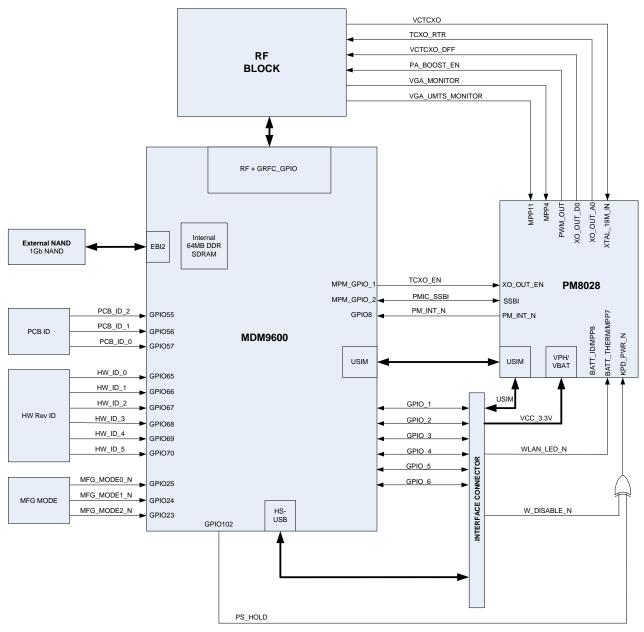


Figure 4-1: System block diagram

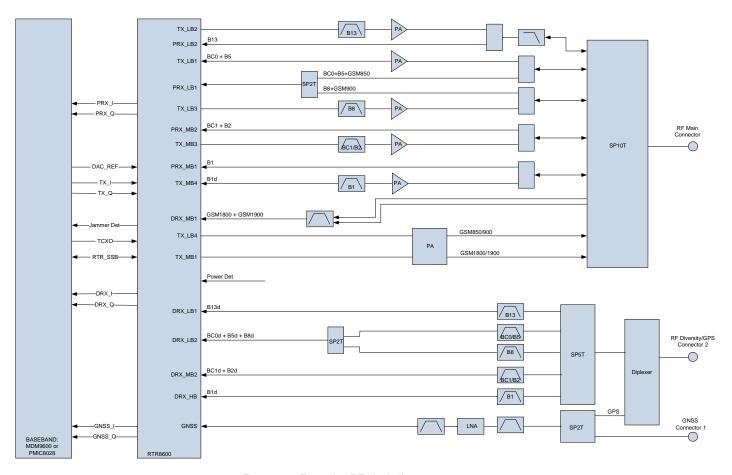


Figure 4-2: Expanded RF block diagram

Host interface pin assignments

The MC7750 host I/O connector provides pins for power, serial communications, and control. Pin assignments are listed in Table 4-1. See the following tables for pin details based on interface types:

- Table 4-2, Power and ground specifications, on page 29
- Table 4-3, USB interface, on page 29
- Table 4-4, SIM interface signal, on page 30
- Table 4-5, Module control signals, on page 33

Note: On any given interface (USB, SIM, etc.), leave unused inputs and outputs as noconnects. Note: The following table describes the **internal** structure of the module. GPIO pins are reserved for future use. For applications not requiring GPIO functionality, leave these pins not connected on the host.

Table 4-1: Connector pin assignments¹

D:	0:	Pin	Description	Direction	Active	V	Voltage levels (V)			
Pin	Signal name	type ²	Description	to module	state	Min	Тур	Max		
1	NC	-	No connect Reserved for future use.	-	-	-	-	-		
2	VCC	٧	3.3 V supply	Input	Power	3.0	3.3	3.6		
3	NC	-	No connect Reserved for future use	-	-	-	-	-		
4	GND	٧	Ground	Input	Power	-	0	-		
5	NC	-	No connect Reserved for future use	-	-	-	-	-		
6	GPIO1	-	General purpose I/O	Input high	-	1.17	1.80	2.10		
				Input low	-	-0.3	-	0.63		
				Output high	-	1.35	-	1.80		
				Output low	-	0	-	0.45		
7	NC	-	No connect	-	-	-	-	-		
8	USIM_PWR	-	SIM VCC supply	Output	Power	2.95 (3V SIM) 1.75 (1.8V SIM)	3.00 (3V SIM) 1.8 (1.8V SIM)	3.05 (3V SIM) 1.85 (1.8V SIM)		
9	GND	٧	Ground	Input	Power	-	0	-		
10	USIM_DATA	-	SIM IO pin	Input	Low	-0.3 (3V SIM) -0.3 (1.8V SIM)	-	1.05 (3V SIM) 0.63 (1.8V SIM)		
					High	1.95 (3V SIM) 1.17 (1.8V SIM)	3.0 (3V SIM) 1.8 (1.8V SIM)	3.3 (3V SIM) 2.1 (1.8V SIM)		
				Output	Low	0	-	0.45		
					High	2.55 (3V SIM) 1.35 (1.8V SIM)	-	3.0 (3V SIM) 1.8 (1.8V SIM)		
11	NC	-	No connect	-	-	-	-	-		
12	USIM_CLK	-	SIM Clock	Output	Low	0	-	0.45		
					High	2.55 (3V SIM) 1.35 (1.8V SIM)	-	3.0 (3V SIM) 1.8 (1.8V SIM)		
13	NC	-	No connect	-	-	-	-	-		

Table 4-1: Connector pin assignments¹ (Continued)

	Din Simual name			Direction	Active	Voltage levels (V)			
Pin	Signal name	type ²	Description	to module	state	Min	Тур	Max	
14	USIM_RST	-	SIM Reset	Output	Low	0	-	0.45	
					High	2.55 (3V SIM) 1.35 (1.8V SIM)	-	3.0 (3V SIM) 1.8 (1.8V SIM)	
15	GND	V	Ground	Input	Power	-	0	-	
16	GPIO2	-	General purpose I/O	Input high	-	1.17	1.80	2.10	
				Input low	-	-0.3	-	0.63	
				Output high	-	1.35	-	1.80	
				Output low	-	0	-	0.45	
17	NC	-	No connect	-	-	-	-	-	
18	GND	V	Ground	Input	Power	-	0	-	
19	NC	-	No connect	-	-	-	-	-	
20	W_DISABLE_N	-	Wireless Disable (main RF radio)	Input	Low	-	-	0.4	
21	GND	V	Ground	Input	Power	-	0	-	
22	NC	-	No connect	-	-	-	-	-	
23	NC	-	No connect	-	-	-	-	-	
24	VCC	V	3.3 V supply	Input	Power	3.0	3.3	3.6	
25	NC	-	No connect	-	-	-	-	-	
26	GND	V	Ground	Input	Power	-	0	-	
27	GND	V	Ground	Input	Power	-	0	-	
28	GPIO3	-	General purpose I/O	Input high	-	1.17	1.80	2.10	
				Input low	-	-0.3	-	0.63	
				Output high	-	1.35	-	1.80	
				Output low	-	0	-	0.45	
29	GND	V	Ground	Input	Power	-	0	-	
30	NC	-	No connect	-	-	-	-	-	
31	NC	-	No connect	-	-	-	-	-	
32	NC	-	No connect	-	-	-	-	-	
33	NC	-	No connect	-	-	-	-	-	
34	GND	V	Ground	Input	Power	-	0	-	
35	GND	V	Ground	Input	Power	-	0	-	
36	USB_D-	-	USB data negative	Input/Output	Differential	-	-	-	

Table 4-1: Connector pin assignments¹ (Continued)

D:	0:	Pin	B	Direction	Active	Voltage levels (V)			
Pin	Signal name	type ²	Description	to module	state	Min	Тур	Max	
37	GND	٧	Ground	Input	Power	-	0	-	
38	USB_D+	-	USB data positive	Input/Output	Differential	-	-	-	
39	VCC	٧	3.3 V supply	Input	Power	3.0	3.3	3.6	
40	GND	٧	Ground	Input	Power	-	0	-	
41	VCC	V	3.3 V supply	Input	Power	3.0	3.3	3.6	
42	WLAN_LED_N	-	LED Driver	Output	Low	0	-	0.45	
43	GND	٧	Ground	Input	Power	-	0	-	
44	GPIO4	-	General purpose I/O	Input high	-	1.17	1.80	2.10	
				Input low	-	-0.3	-	0.63	
				Output high	-	1.35	-	1.80	
				Output low	-	0	-	0.45	
45	NC	-	No connect	-	-	-	-	-	
46	GPIO5	-	General purpose I/O	Input high	-	1.17	1.80	2.10	
				Input low	-	-0.3	-	0.63	
				Output high	-	1.35	-	1.80	
				Output low	-	0	-	0.45	
47	NC	-	No connect	-	-	-	-	-	
48	GPIO6	-	General purpose I/O	Input high	-	1.17	1.80	2.10	
				Input low	-	-0.3	-	0.63	
				Output high	-	1.35	-	1.80	
				Output low	-	0	-	0.45	
49	NC	-	No connect	-	-	-	-	-	
50	GND	٧	Ground	Input	Power	-	0	-	
51	NC	-	No connect Reserved for future use	-	-	-	-	-	
52	VCC	V	3.3 V supply	Input	Power	3.0	3.3	3.6	

The host should leave all 'NC' ('no connect) pins unconnected.
 A—Analog; I—Input; NP—No pull; O—Digital output; PU—Digital input (internal pull up); PD—Digital output (internal pull down); V—Power or ground

Power supply

The host provides power to the MC7750 through multiple power and ground pins as summarized in Table 4-2.

The host must provide safe and continuous power at all times; the module does not have an independent power supply, or protection circuits to guard against electrical issues.

Table 4-2: Power and ground specifications

Name	Pins	Specification	Min	Тур	Max	Units
VCC	2, 24, 39, 41, 52	Voltage range	See Table 4-1 on page 26.			•
		Ripple voltage	-	-	100	mV_{pp}
GND	4, 9, 15, 18, 21, 26, 27, 29, 34, 35, 37, 40, 43, 50	-	-	0	-	V

USB interface

The USB interface is the path for communication between the host and module.

The interface complies with the [12] Universal Serial Bus Specification, Rev 2.0, and the host device must be designed to the same standard. (When designing the host device, careful PCB layout practices must be followed.)

Table 4-3: USB interface

Name	Pin	Description
USB_D-	36	USB data negative
USB_D+	38	USB data positive

USB interface features include:

- Data rate: Full-speed (12 Mbps)/High-speed (480 Mbps)
- Module enumeration:
 - · Windows: Modem or COM ports, using host Windows drivers
 - Linux: /dev/ttyUSBn devices for Linux systems with the Sierra Wireless driver installed
- USB-compliant transceivers
- Selective suspend mode
- Resumption initiated by host or module

USB high/full speed throughput performance

This device has been designed to achieve optimal performance and maximum throughput using USB high speed mode. Although the device may operate with a full speed host, throughput performance will be on an "as is" basis and needs to

be characterized by the OEM. Note that throughput will be reduced and may vary significantly based on packet size, host interface, and firmware revision. Sierra Wireless does not recommend using this device in USB full speed mode.

User-developed drivers

If you will be developing your own USB drivers, see [5] AirCard/AirPrime USB Driver Developer's Guide (Doc# 2130634).

SIM interface

The module supports one SIM (Subscriber Identity Module) (1.8 V or 3 V). The SIM holds account information, allowing users to use their account on multiple devices.

The SIM pins (Table 4-4) provide the connections necessary to interface to a SIM socket located on the host device as shown in Figure 4-3 on page 31. Voltage levels over this interface comply with 3GPP standards.

Table 4-4: SIM interface signal

Name	Pin	Description	SIM contact number ¹	Notes
USIM_PWR	8	SIM voltage	1	Power supply for SIM
USIM_DATA	10	Data I/O	7	Bi-directional SIM data line
USIM_CLK	12	Serial clock	3	Serial clock for SIM data
USIM_RST	14	Reset	2	Active low SIM reset
USIM_GND		Ground	5	Ground reference USIM_GND is common to module ground

^{1.} See Figure 4-4 on page 31 for SIM card contacts.

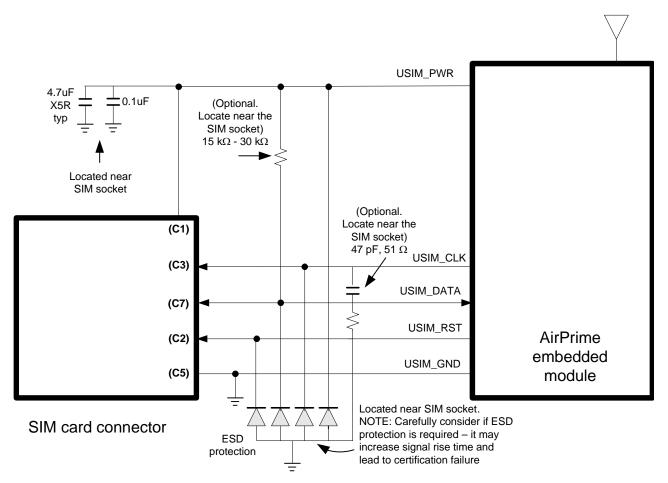


Figure 4-3: SIM application interface

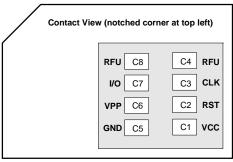


Figure 4-4: SIM card contacts (contact view)

SIM implementation

Note: For interface design requirements, refer to: (2G) 3GPP TS 51.010-1, section 27.17, or (3G) ETSI TS 102 230 V5.5.0, section 5.2.

When designing the remote SIM interface, you *must* make sure that SIM signal integrity is not compromised.

Some design recommendations include:

- Total impedance of the VCC and GND connections to the SIM, measured at the module connector, should be less than 1 Ω to minimize voltage drop (includes any trace impedance and lumped element components—inductors, filters, etc.).
- Position the SIM connector ≤10 cm from the module. If a longer distance is
 required because of the host device design, use a shielded wire assembly—
 connect one end as close as possible to the SIM connector and the other end
 as close as possible to the module connector. The shielded assembly may
 help shield the SIM interface from system noise.
- Reduce crosstalk on the USIM_DATA line to reduce the risk of failures during GCF approval testing.
- Avoid routing the USIM_CLK and USIM_DATA lines in parallel over distances
 >2 cm—cross-coupling of these lines can cause failures.
- 3GPP has stringent requirements for I/O rise time (<1 μ s), signal level limits, and noise immunity—consider this carefully when developing your PCB layout.
 - Keep signal rise time <1 µs—keep USIM signals as short as possible, and keep very low capacitance traces on the USIM_DATA and USIM_CLK signals. High capacitance increases signal rise time, potentially causing your device to fail certification tests.
- Add external pull-up resistors (15 k Ω –30 k Ω), if required, between the USIM_DATA and USIM_PWR lines to optimize the signal rise time.
- VCC line should be decoupled close to the SIM socket.
- SIM is specified to run up to 5 MHz (SIM clock rate). Take note of this speed in the placement and routing of the SIM signals and connectors.
- You must decide whether additional ESD protection is required for your product, as it is dependent on the application, mechanical enclosure, and SIM connector design. The SIM pins will require additional ESD protection if they are exposed to high ESD levels (i.e. can be touched by a user).
- Putting an optional decoupling capacitor at USIM_PWR near the SIM socket is recommended—the longer the trace length (impedance) from the socket to the module, the greater the capacitance requirement to meet compliance tests.
- Putting an optional series capacitor and resistor termination (to ground) at USIM_CLK at the SIM socket to reduce EMI and increase signal integrity is recommended if the trace length between the SIM socket and module is long—47 pF and 50 Ω resistor are recommended.
- Test your first prototype host hardware with a Comprion IT³ SIM test device at a suitable testing facility.

Control interface (Signals)

The MC7750 provides signals for:

- Power control of the module from the host
- LED driver output

These signals are summarized in Table 4-5 and paragraphs that follow.

Table 4-5: Module control signals

Name	Pin	Description	Type ¹
W_DISABLE_N	20	Wireless disable (Main RF)	PU
WLAN_LED_N	42	LED driver	0

^{1.} O—Digital pin Output; PU—Digital pin Input, internal pull up

W_DISABLE_N — Wireless disable

The host device uses W_DISABLE_N (pin 20) to enable/disable the WWAN or radio modem. When disabled, the modem cannot transmit or receive information.

Letting this signal float high allows the module to operate normally. This switch follows the behavior described in [11] PCI Express Mini Card Electromechanical Specification Revision 1.2. This pin has a 20 k Ω pull-up resistor. See Figure 4-5 on page 33 for a recommended implementation.

When integrating with your host device, keep the following in mind:

- The signal is an input to the module and should be driven LOW only for its
 active state (controlling the power state); otherwise it should be floating or
 (High impedance). It should never be driven to a logic high level. The module
 has an internal pull-up resistor to Module Power (3.3V) in place, so if the
 signal is floating or (high impedance), the module will power on.
- Wait for two seconds after asserting W_DISABLE_N before disconnecting power.
- If the host never needs to assert this power state control to the module, leave this signal unconnected from the host interface.

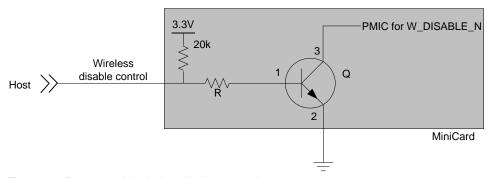


Figure 4-5: Recommended wireless disable connection

WLAN_LED_N—LED output

The module drives the LED output according to [11] PCI Express Mini Card Electromechanical Specification Revision 1.2, as described in Table 4-6 (below).

If desired, LED behavior can be configured using AT!LEDCTRL.

Table 4-6: LED states (Default behavior)

LED beh		ehavior			!LEDCTRL
State	Period (s)	On	Off	Description	index
Off	0	0%	100%	Module is not powered. (W_DISABLE_N asserted with PCOFFEN=1)	N/A
Airplane mode	2	50%	50%	Module is in low power mode. (W_DISABLE_N asserted with PCOFFEN=0)	4
Power up	5.2	96%	4%	Module is performing initial power up activities.	N/A
Searching		96%	4%	Module is searching service.	1
Connected	0.5	80%	20%	Module has an active context.	3
Connected, with data transfer occuring	0.5	80%	20%	Module has an active context and data is being transferred.	5
Error	1.6	20%	80%	Device error has occurred.	N/A
Attached	1	100%	0%	Module has attached to a network and is not currently in a call.	2

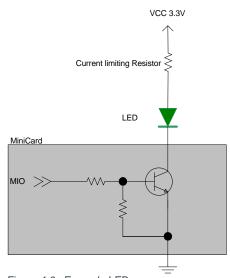


Figure 4-6: Example LED

Digital interface

The MC7750 Mini Card provides the general purpose digital I/O (GPIO) signals listed in Table 4-7:

- By default, all GPIO pins are set as inputs.
- Voltage should not be applied until > 1s after VCC is applied to the minicard.
- GPIO pins are available for OEM-defined purposes but may, in future firmware releases, be allocated by Sierra Wireless for specific functionality.
- For applications not requiring GPIO functionality, leave these pins not connected on the host.

Table 4-7: GPIO signals

Name	Pin	Description	Type ^{1,2}
GPIO1	6	General purpose IO	PD
GPIO2	16	General purpose IO	PD
GPIO3	28	General purpose IO	PD
GPIO4	44	General purpose IO	PD
GPIO5	46	General purpose IO	PD
GPIO6	48	General purpose IO	PD

- GPIO pins are initialized as PD by the firmware.
 PD—Digital pin Input, internal pull down

>>> 5: RF Specifications

The MC7750 includes three RF connectors for use with host-supplied antennas:

- Main RF connector—Rx/Tx path
- GPS connector 1—Standalone GPS
- Diversity/MIMO/GPS connector 2—Diversity, MIMO, or GPS

The module does not have integrated antennas.

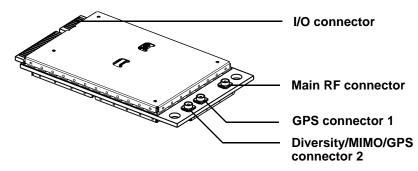


Figure 5-1: Module connectors

RF connections

When attaching antennas to the module:

when attaching antennas to the module

on the module, as shown in Figure 5-1 on page 37. • Match coaxial connections between the module and the antenna to 50 Ω

Use Hirose U.FL connectors (3 mm x 3 mm, low profile; model

U.FL #CL331-0471-0-10) to attach antennas to connection points

- Minimize RF cable losses to the antenna; the recommended maximum cable loss for antenna cabling is 0.5 dB.
- To ensure best thermal performance, if possible use the mounting holes to attach (ground) the device to the main PCB ground or a metal chassis.

Note: If the antenna connection is shorted or open, the modem will not sustain permanent damage.

Shielding

The module is fully shielded to protect against EMI and must not be removed.

Note: To **disconnect** the antenna, make sure you use the Hirose U.FL connector removal tool (P/N UFL-LP-N-2(01)) to prevent damage to the module or coaxial cable assembly.

Antenna and cabling

When selecting the antenna and cable, it is critical to RF performance to match antenna gain and cable loss.

Note: For detailed electrical performance criteria, see Appendix A: Antenna Specification on page 65.

Choosing the correct antenna and cabling

When matching antennas and cabling:

- The antenna (and associated circuitry) should have a nominal impedance of 50 Ω with a return loss of better than 10 dB across each frequency band of operation.
- The system gain value affects both radiated power and regulatory (FCC, IC, CE, etc.) test results.

Designing custom antennas

Consider the following points when designing custom antennas:

- A skilled RF engineer should do the development to ensure that the RF performance is maintained.
- If both CDMA and UMTS modules will be installed in the same platform, you may want to develop separate antennas for maximum performance.

Determining the antenna's location

When deciding where to put the antennas:

- Antenna location may affect RF performance. Although the module is shielded to prevent interference in most applications, the placement of the antenna is still very important—if the host device is insufficiently shielded, high levels of broadband or spurious noise can degrade the module's performance.
- Connecting cables between the module and the antenna must have 50 Ω impedance. If the impedance of the module is mismatched, RF performance is reduced significantly.
- Antenna cables should be routed, if possible, away from noise sources (switching power supplies, LCD assemblies, etc.). If the cables are near the noise sources, the noise may be coupled into the RF cable and into the antenna. See Interference from other wireless devices on page 39.

Disabling the diversity antenna

- For LTE bands, use the AT command !RXDEN=0 to disable receive diversity or !RXDEN=1 to enable receive diversity.
- For CDMA bands, use the AT command !DIVERSITY to enable or disable receive diversity.

Note: A diversity antenna is used to improve connection quality and reliability through redundancy. Because two antennas may experience difference interference effects (signal distortion, delay, etc.), when one antenna receives a degraded signal, the other may not be similarly affected.

Ground connection

When connecting the module to system ground:

- Prevent noise leakage by establishing a very good ground connection to the module through the host connector.
- Connect to system ground using the two mounting holes at the top of the module (shown in Figure 5-1 on page 37).
- Minimize ground noise leakage into the RF.
 Depending on the host board design, noise could *potentially* be coupled to the module from the host board. This is mainly an issue for host designs that have signals traveling along the length of the module, or circuitry operating at both ends of the module interconnects.

Interference and sensitivity

Several interference sources can affect the module's RF performance (RF desense). Common sources include power supply noise and device-generated RF.

RF desense can be addressed through a combination of mitigation techniques (Methods to mitigate decreased Rx performance on page 40) and radiated sensitivity measurement (Radiated sensitivity measurement on page 41).

Note: The MC7750 is based on ZIF (Zero Intermediate Frequency) technologies. When performing EMC (Electromagnetic Compatibility) tests, there are no IF (Intermediate Frequency) components from the module to consider.

Interference from other wireless devices

Wireless devices operating inside the host device can cause interference that affects the module.

To determine the most suitable locations for antennas on your host device, evaluate each wireless device's radio system, considering the following:

- Any harmonics, sub-harmonics, or cross-products of signals generated by wireless devices that fall in the module's Rx range may cause spurious response, resulting in decreased Rx performance.
- The Tx power and corresponding broadband noise of other wireless devices may overload or increase the noise floor of the module's receiver, resulting in Rx desense.

The severity of this interference depends on the closeness of the other antennas to the module's antenna. To determine suitable locations for each wireless device's antenna, thoroughly evaluate your host device's design.

Host-generated RF interference

All electronic computing devices generate RF interference that can negatively affect the receive sensitivity of the module.

Proximity of host electronics to the antenna in wireless devices can contribute to decreased Rx performance. Components that are most likely to cause this include:

- Microprocessor and memory
- Display panel and display drivers
- Switching-mode power supplies

Device-generated RF interference

The module can cause interference with other devices. Wireless devices such as AirPrime embedded modules transmit in bursts (pulse transients) for set durations (RF burst frequencies). Hearing aids and speakers convert these burst frequencies into audible frequencies, resulting in audible noise.

Methods to mitigate decreased Rx performance

It is important to investigate sources of localized interference early in the design cycle. To reduce the effect of device-generated RF on Rx performance:

- Put the antenna as far as possible from sources of interference. The drawback is that the module may be less convenient to use.
- Shield the host device. The module itself is well shielded to avoid external
 interference. However, the antenna cannot be shielded for obvious reasons.
 In most instances, it is necessary to employ shielding on the components of
 the host device (such as the main processor and parallel bus) that have the
 highest RF emissions.
- Filter out unwanted high-order harmonic energy by using discrete filtering on low frequency lines.
- Form shielding layers around high-speed clock traces by using multi-layer PCBs.
- Route antenna cables away from noise sources.

Radiated Spurious Emissions (RSE)

When designing an antenna for use with AirPrime embedded modules, the host device with an AirPrime embedded module must satisfy the radiated spurious emission (RSE) test cases described in:

• (CDMA) Refer to CDMA standards for receive-only mode, and local regulatory bodies for transmit mode (transmitter is operating).

Note that antenna impedance affects radiated emissions, which must be compared against the conducted 50-ohm emissions baseline. (AirPrime embedded modules meet the 50-ohm conducted emissions requirement.)

Radiated sensitivity measurement

A wireless host device contains many noise sources that contribute to a reduction in Rx performance.

To determine the extent of any receiver performance desensitization due to selfgenerated noise in the host device, over-the-air (OTA) or radiated testing is required. This testing can be performed by Sierra Wireless or you can use your own OTA test chamber for in-house testing.

Sierra Wireless' sensitivity testing and desensitization investigation

Although AirPrime embedded modules are designed to meet carrier requirements for receiver performance, they are still susceptible to various performance inhibitors.

As part of the Engineering Services package, Sierra Wireless offers modem OTA sensitivity testing and desensitization (desense) investigation. For more information, contact your account manager or the Sales Desk (see Contact Information on page 4).

Note: Sierra Wireless has the capability to measure TIS (Total Isotropic Sensitivity) and TRP (Total Radiated Power) according to CTIA's published test procedure.

Sensitivity vs. frequency

For CDMA bands, sensitivity is defined as the input power level in dBm that produces a FER (Frame Error Rate) of 0.5%. Sensitivity should be measured at all CDMA frequencies across each band.

For LTE bands, sensitivity is defined as the RF level at which throughput is 95% of maximum.

Supported frequencies

The MC7750 supports:

- Single-band LTE—See Table 5-1 on page 42.
- Dual-band CDMA—See Table 5-3 on page 42.
- GPS
- Radio transceiver requirements for 3GPP Release 7

 Inter-RAT and inter-frequency cell reselection and handover between supported frequency bands

Table 5-1: LTE frequency band support

Band	Frequencies
Band 13	Tx: 777–787 MHz Rx: 746–756 MHz

Table 5-2: LTE bandwidth support¹

Band	1.4 MHz	3 MHz	5 MHz	10 MHz	15 MHz	20 MHz
Band 13	X	X	√ ²	√ ²	×	X

- 1. Table contents are derived from 3GPP TS 36.521-1 v9.4.1, table 5.4.2.1-1.
- 2. Bandwidth for which a relaxation of the specified UE receiver sensitivity requirement (Clause 7.3 of 3GPP TS 36.521-1 v9.4.1) is allowed.

Table 5-3: CDMA frequency band support

Band	Frequencies
PCS	Tx: 1850–1910 MHz Rx: 1930–1990 MHz
Cellular	Tx: 824–849 MHz Rx: 869–894 MHz

Conducted Rx sensitivity / Tx power

Table 5-4: Conducted Rx (Receive) sensitivity—LTE bands

		C	onducted Rx s	Rx sensitivity (dBm)			
LTE bands		Primary (Typical)	Secondary SIMO (Typical) (Typical)		SIMO ¹ (Worst case)		
LTE Band 13	Full RB BW: 10 MHz ²	-97.0 ³	-96.5 ³	-100.0 ³	-93.3		

- Per 3GPP specification
- Sensitivity values scale with bandwidth: x_MHz_Sensitivity = 10 MHz_Sensitivity - 10*log(10 MHz/x_MHz)
- 3. Verizon Test Method

Table 5-5: Conducted Rx (Receive) sensitivity — CDMA bands

CDMA bands		Conducted Rx sensitivity (dBm)				
CDMA Dallus		Typical	Worst case			
Cellular (800 MHz)	CDMA 1x 0.5% FER	-108.0	-104.0			
Celidiai (000 ivii 12)	EVDO rev A 0.5% PER	-110.0	-105.5			

Table 5-5: Conducted Rx (Receive) sensitivity—CDMA bands

CDMA bands		Conducted Rx sensitivity (dBm)			
CDMA Dallus		Typical	Worst case		
PCS (1900 MHz)	CDMA 1x 0.5% FER	-107.5	-104.0		
1 03 (1900 WI12)	EVDO rev A 0.5% PER	-109.5	-105.5		

Table 5-6: Conducted Tx (Transmit) power tolerances

Parameter	Conducted transmit power (dBm) ¹	Notes
LTE		
LTE, Band 13	+23 dBm ± 1dB	
CDMA		
CDMA Band Class 0 (Cellular)	+24 dBm ± 1dB	
CDMA Band Class 1 (PCS)	+23.5 dBm ± 1dB (channel 1175)	
	+24 dBm ± 1dB (other channels)	

^{1.} Preliminary values

GPS specifications

Note: For detailed electrical performance criteria, see Recommended GPS antenna specifications on page 67.

Table 5-7: GPS specifications ¹

Parameter/feature	Description
Satellite channels	12 channel, continuous tracking
Protocols	NMEA 0183 V3.0
Acquisition time	Hot start: 1 s Warm start: 29 s Cold start: 32 s
Accuracy	Horizontal: < 2 m (50%); < 5 m (90%) Altitude: < 4 m (50%); < 8 m (90%) Velocity: < 0.2 m/s

Table 5-7: GPS specifications (Continued)¹

Parameter/feature	Description
Sensitivity	Tracking ² : -161 dBm Acquisition ³ (Assisted, non-LTE): -158 dBm Acquisition (Assisted, LTE): -153 dBm Acquisition (Standalone): -145 dBm
Operational limits	Altitude <6000 m or velocity <100 m/s (Either limit may be exceeded, but not both.)

- All values are preliminary.
 Tracking sensitivity is the lowest GPS signal level for which the device can still detect an in-view satellite 98% of the time when in sequential tracking mode.
 Acquisition sensitivity is the lowest GPS signal level for which the device can still detect
- an in-view satellite 50% of the time.

44

Power consumption

Note: All specifications in these tables are preliminary, based on chipset published expectations. Power consumption measurements in the tables below are for the MC7750 Mini Card module connected to the host PC via USB.

The module does not have its own power source and depends on the host device for power. For a description of input voltage requirements, see Power supply on page 29.

Table 6-1: Averaged standby DC power consumption¹

Signal	Description	Bands ²	Current ³			Notes /			
Signal			Тур	Max ⁴	Unit	configuration			
VCC	Standby current consumption (Sleep mode activated ⁵)								
	LTE	LTE Bands	5.5	8	mA				
	CDMA EVDO	CDMA bands	6	9.5	mA				
	Standby current consumption (Sleep mode deactivated ⁵)								
	LTE	LTE bands	55	65	mA				
	CDMA EVDO	CDMA bands	58	65	mA				
	Low Power Mode (LPM)/Offline Mode (Sleep mode activated ⁵)								
	RF disabled, but module	is operational	2.5	3.0	mA				
	Low Power Mode (LPM)/Offline Mode (Sleep mode deactivated ⁵)								
	RF disabled, but module	is operational	67	80	mA				

- 1. 3.3V supply voltage
- 2. For supported bands, see Table 5-1, LTE frequency band support, on page 42 and Table 5-3, CDMA frequency band support, on page 42.
- 3. All measurements are preliminary.
- 4. Measured at 30°C/nominal voltage.
- 5. Assumes USB bus is fully suspended during measurements

Table 6-2: CDMA DC power consumption (+3.3V)

Description	Bands	Тур	Max	Units	Notes / configuration
IS-2000 1X Data current	PCS	366	-	mA	SO32, RC3 (Fwd) / RC3 (Rvs), 153.6 kbps (Fwd) / 76.8 kbps (Rvs), CDG Urban Profile, USB active
		423	-	mA	SO32, RC3 (Fwd) / RC3 (Rvs), 153.6 kbps (Fwd) / 76.8 kbps (Rvs), CDG Suburban Profile, USB active
	Cellular	327	-	mA	SO32, RC3 (Fwd) / RC3 (Rvs), 153.6 kbps (Fwd) / 76.8 kbps (Rvs), CDG Urban Profile, USB active
		370	-	mA	SO32, RC3 (Fwd) / RC3 (Rvs), 153.6 kbps (Fwd) / 76.8 kbps (Rvs), CDG Suburban Profile, USB active
IS-856 1xEV-DO Revision 0 Data current	PCS	404	-	mA	CDG Urban Profile, USB active
		475	-	mA	CDG Suburban Profile, USB active
	Cellular	324	-	mA	CDG Urban Profile, USB active
		377	-	mA	CDG Suburban Profile, USB active
IS-856A 1xEV-DO Revision A Data current	PCS	408	-	mA	CDG Urban Profile, USB active
		479	-	mA	CDG Suburban Profile, USB active
	Cellular	331	-	mA	CDG Urban Profile, USB active
		386	-	mA	CDG Suburban Profile, USB active
Maximum peak current – operational	PCS or Cellular		1.2	A	Max RF output power, full rate, full operating temperature range.
Maximum peak current – call connected			1.0	А	Max RF output power, full rate, full operating temperature range

Table 6-3: Averaged call mode DC power consumption (LTE)¹

Signal	Description	D 12	Current Max ³ Unit		Notes / configuration		
Signal	Description	Band ²					
VCC	Data current consumption (includes USB bus current)						
	LTE category 3	LTE bands	550	mA	100/50 Mbps—0 dBm Tx power		

- 1. All measurements are preliminary values
- For supported bands, see Table 5-1, LTE frequency band support, on page 42 and Table 5-3, CDMA frequency band support, on page 42.
 Measured at 30°C/nominal voltage.

Table 6-4: Miscellaneous DC power consumption¹

Signal	Description	Current		Unit	Notes/configuration	
Sigilal	Description	Тур	Max	Ollit	Notes/ configuration	
	Module OFF leakage current	490	830	μΑ	Full operating temperature range	
VCC	USB active current	18	25	mA	High speed USB connection, $C_L = 50 \text{ pF}$ on D+ and D- signals	
VCC	Inrush current	750	3000	mA	 Assumes power supply turn on time > 100µs Dependent on host power supply rise time. 	
GPS signal connector	Active bias on GPS port		3.3 (100 mA)	V	GPS connector 1 in Figure 5-1 on page 37.	

^{1.} All measurements are preliminary values

Module power states

The module has five power states, as described in Table 6-5.

Table 6-5: Module power states

State	Details	Host is powered	Module is powered	USB interface active	RF enabled
Normal (Default state)	 Module is active Default state when VCC is first applied in the absence of W_DISABLE_N control Module is capable of placing/receiving calls, or establishing data connections on the wireless network Current consumption is affected by several factors, including: Radio band being used Transmit power Receive gain settings Data rate Number of active Tx time slots 	V	V	V	V
Low power ('Airplane mode')	Module is active State is controlled by host interface using software commands: +CFUN=0 ([1] AT Command Set for User Equipment (UE) (Release 6) (Doc# 3GPP TS 27.007)))	~	~	~	×
Sleep	 Normal state of module between calls or data connections Module cycles between wake (polling the network) and sleep, at network provider-determined interval. 	~	~	X	×

Table 6-5: Module power states (Continued)

State	Details	Host is powered	Module is powered	USB interface active	RF enabled
Off	 Host keeps module powered off by driving W_DISABLE_N low Module draws minimal current See W_DISABLE_N — Wireless disable on page 33 for more information.] 	~	X	X	×
Disconnected	Host power source is disconnected from the module and all voltages associated with the module are at 0 V.	X	×	×	X

Power state transitions

The module uses state machines to monitor supply voltage and operating temperature, and notifies the host when critical threshold limits are exceeded. (See Table 6-6 for trigger details and Figure 6-1 for state machine behavior.)

Power state transitions may occur:

- Automatically, when critical supply voltage or module temperature trigger levels are encountered.
- Under host control, using available AT commands in response to user choices (for example, opting to switch to airplane mode) or operating conditions.

Table 6-6: Power state transitions (including voltage/temperature trigger levels)

Transition	Voltage		Temperature ¹		Notes	
Hansilion	Trigger	V ²	Trigger	°C	Notes	
Normal to Low Power	VOLT_HI_CRIT	3.6	TEMP_LO_CRIT	-25	RF activity suspended	
Normal to Low Fower	VOLT_LO_CRIT	2.9	TEMP_HI_CRIT	95	Tractivity suspended	
Low Power to Normal	VOLT_HI_NORM	3.5	TEMP_NORM_LO	-15		
Low Power to Normal or Remain in Normal (Remove warnings)	VOLT_LO_NORM	3.1	TEMP_HI_NORM	80	RF activity resumed	
Normal (Issue warning)	VOLT_LO_WARN	3.0	TEMP_HI_WARN	85		
Power off/on (Host-initiated)	-	-	-	-	Power off recommended when supply voltage or module operating temperature is critically low or high.	

- 1. Module-reported temperatures at the printed circuit board.
- 2. Supply voltage—3.3V

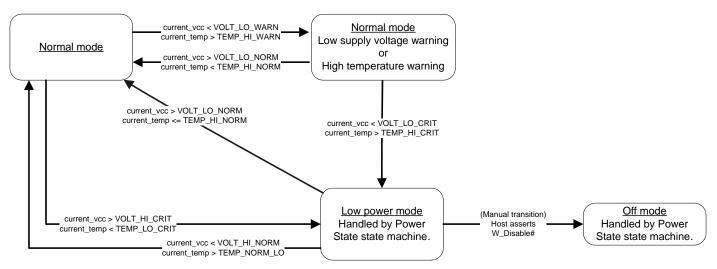


Figure 6-1: Voltage/temperature monitoring state machines

Power interface

Power ramp-up

On inital power up, inrush current depends on the power supply rise time—turn on time $>100~\mu s$ is required for <3A inrush current.

The supply voltage must remain within specified tolerances while this is occurring.

Power-up timing

The unit is ready to enumerate with a USB host within a maximum of 3–5 seconds after power-up. Figure 6-2 on page 49 illustrates the power-up timing sequence.

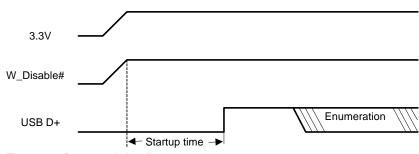


Figure 6-2: Power-up timing diagram

Note: Startup time is the time after power-up when the modem is ready to begin the enumeration sequence.

Power supply noise

Noise in the power supply can lead to noise in the RF signal.

The power supply ripple limit for the module is no more than 200 mVp-p 1 Hz to 100 kHz. This limit includes voltage ripple due to transmitter burst activity.

Additional decoupling capacitors can be added to the main VCC line to filter noise into the device.

SED (Smart Error Detection)

The module uses a form of SED to track premature modem resets.

- Module tracks consecutive resets occuring soon after power-on.
- After a sixth consecutive reset, the module waits in boot-and-hold mode for a firmware download to resolve the power-cycle problem.

>> 7: Software Interface

Support tools

The MC7750 is compatible with the following support tools from Sierra Wireless and authorized third parties:

- Firmware update utilities from Sierra Wireless
- Sierra Wireless Product Support Tool (SW-PST)
- CDMA Air Interface Tool (CAIT) from QUALCOMM
- QXDM from QUALCOMM
- QUALCOMM Product Support Tool (QPST)

USB interface

The device supports the Qualcomm QMI interface.

Please contact your Sierra Wireless account representative for QMI interface documentation.

MTU size

The MTU (Maximum Transmission Unit) size is configured using a driver installer command line option:

MTUSize=<value> (<value> is the size in bytes)

Verizon Wireless requires the MTU size to be 1428 bytes.

Example:

driverinstaller /MTUSize=1428

TCP window size (Windows XP)

The TCP window size for Windows XP is 128 kB (131072 bytes).

>>> 8: Mechanical and Environmental Specifications

The MC7750 module complies with the mechanical and environmental specifications in Table 8-1. Final product conformance to these specifications depends on the OEM device implementation.

Table 8-1: Mechanical and environmental specifications

	Mode	Details	
Temperature	Operational	-30°C to +60°C – Full RF compliance	
	Non-operational	-40°C to +85°C, 96 hours (from MIL-STD 202 Method 108)	
Relative humidity	Non-operational	85°C, 85% relative humidity for 48 hours (non-condensing)	
Vibration	Non-operational	Random vibration, 10 to 1000 Hz, nominal 6 G rms in each of three mutually perpendicular axes. Test duration of 60 minutes for each axis, for a total test time of three hours.	
Shock	Non-operational	Half sine shock, 2 ms, 180 in/s (375 g). Tested in each of three mutually perpendicular axes, positive and negative (5 x 6, 30 bumps total).	
Drop	Non-operational	1 m on concrete on each of six faces, two times (module only).	
(Electrostatic discharge (See Electrostatic discharge (ESD) on page 55.)	Operational	The RF port (antenna launch and RF connector) complies with the IEC 61000-4-2 standard: • Electrostatic Discharge Immunity: Test: Level3 Contact Discharge: ±6 kV Air Discharge: ±8 kV	
	Non-operational	The host connector Interface complies with the following standards only: +/- 1 kV Human Body Model (JESD22-A114-B) +/- 125 V Charged Device Model (JESD22-C101)	
Thermal considerations		See Thermal considerations on page 56.	
Form factor		PCI-Express Mini Card shielded with metal and metalized fabric	
Dimensions		Length: 50.95 mm Width: 30 mm Thickness: 4.75 mm Weight: Approximately 10 g	

Device views

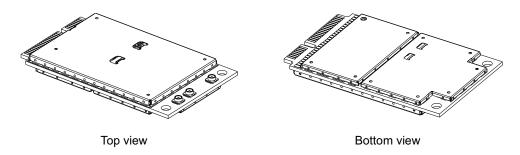


Figure 8-1: Top and bottom views

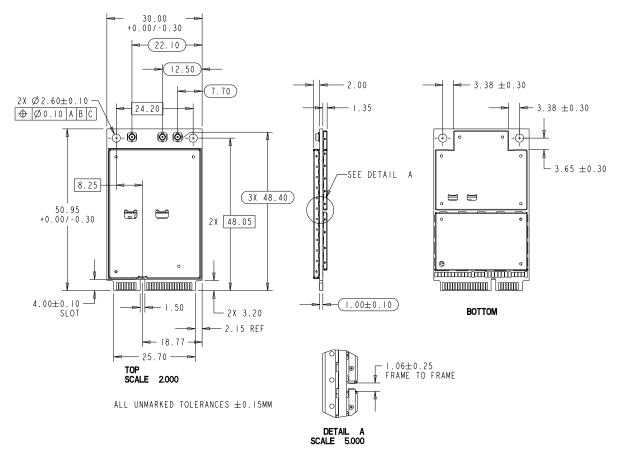


Figure 8-2: Dimensioned view

Labeling



Figure 8-3: Unit label

Note: The displayed label is an example only. The production label will vary by SKU.

The MC7750 label is non-removable and contains:

- Sierra Wireless logo and product name
- IMEI number in Code-128 barcode format
- SKU number (when required)
- Factory Serial Number (FSN) in alphanumeric format
- Manufacturing date code (incorporated into FSN)
- Licensed vendor logo
- Certification marks/details

Note: The MC7750 supports OEM partner-specific label requirements.

Electrostatic discharge (ESD)

The OEM is responsible for ensuring that the Mini Card host interface pins are not exposed to ESD during handling or normal operation. (See Table 8-1 on page 53 for specifications.)

ESD protection is highly recommended for the SIM connector at the point where the contacts are exposed, and for any other signals from the host interface that would be subjected to ESD by the user of the product. (The device includes ESD protection on the antenna.)

Thermal considerations

Embedded modules can generate significant amounts of heat that must be dissipated in the host device for safety and performance reasons.

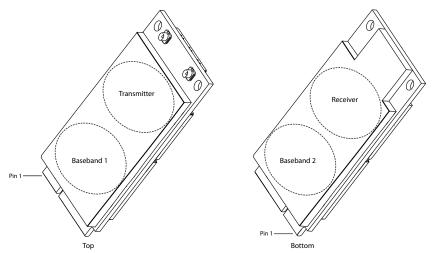


Figure 8-4: Shield locations

The amount of thermal dissipation required depends on:

- Supply voltage—See Chapter 6: Power on page 45 for details of max power dissipation for various operating modes.
- Usage—Typical power dissipation values depend on the location within the host, amount of data transferred, etc.

Specific areas requiring heat dissipation are shown in Figure 8-4:

- Transmitter—Top face of module near RF connectors. Likely to be the hottest area.
- Baseband 1—Top face of module, below the transmitter.
- Receiver—Bottom face of module, behind the transmitter.
- Baseband 2—Bottom face of module, behind Baseband 1.

To enhance heat dissipation:

- Maximize airflow over/around the module.
- Locate the module away from other hot components.
- If possible, use the mounting holes to attach (ground) the device to the main PCB ground or a metal chassis.

Note: Adequate dissipation of heat is necessary to ensure that the module functions properly, and to comply with the thermal requirements in [11] PCI Express Mini Card Electromechanical Specification Revision 1.2.

Caution: Thermal putty is not recommended—incorrect application of the material could require exessive pressure to be applied when seating the board, resulting in damage to the board.

Module integration testing

When testing your integration design:

- Test to your worst case operating environment conditions (temperature and voltage)
- Test using worst case operation (transmitter on 100% duty cycle, maximum power)
- Monitor temperature at all shield locations. Attach thermocouples to the areas indicated in Figure 8-4 on page 56 (Transmitter, Baseband 1, Receiver, Baseband 2).

Note: Make sure that your system design provides sufficient cooling for the module. RF shield temperature should be kept below 90°C when integrated to prevent damage to the module's components.

(For acceptance, certification, quality, and production (including RF) test suggestions, see Testing on page 71.)

>>> 9: Regulatory and Industry Approvals

This module is designed to and, upon commercial release, will be certified to meet carrier requirements (e.g. Verizon Wireless).

Upon commercial release, the following regulatory approvals will have been attained:

- FCC
- IC (Industry Canada)

Upon commercial release, the following industry approvals will have been obtained:

GCF-CC (may be obtained upon customer request)

Additional approvals may be obtained upon customer request—contact your Sierra Wireless account representative for details.

Additional testing and certification may be required for the end product with an embedded MC7750 modem and are the responsibility of the OEM. Sierra Wireless offers professional services-based assistance to OEMs with the testing and certification process, if required.

Important notice

Because of the nature of wireless communications, transmission and reception of data can never be guaranteed. Data may be delayed, corrupted (i.e., have errors) or be totally lost. Although significant delays or losses of data are rare when wireless devices such as the Sierra Wireless modem are used in a normal manner with a well-constructed network, the Sierra Wireless modem should not be used in situations where failure to transmit or receive data could result in damage of any kind to the user or any other party, including but not limited to personal injury, death, or loss of property. Sierra Wireless and its affiliates accept no responsibility for damages of any kind resulting from delays or errors in data transmitted or received using the Sierra Wireless modem, or for failure of the Sierra Wireless modem to transmit or receive such data.

Safety and hazards

Do not operate your MC7750 modem:

- In areas where blasting is in progress
- Where explosive atmospheres may be present including refuelling points, fuel depots, and chemical plants
- Near medical equipment, life support equipment, or any equipment which may be susceptible to any form of radio interference. In such areas, the MC7750 modem MUST BE

POWERED OFF. Otherwise, the MC7750 modem can transmit signals that could interfere with this equipment.

In an aircraft, the MC7750 modem **MUST BE POWERED OFF**. Otherwise, the MC7750 modem can transmit signals that could interfere with various onboard systems and may be dangerous to the operation of the aircraft or disrupt the cellular network. Use of a cellular phone in an aircraft is illegal in some jurisdictions. Failure to observe this instruction may lead to suspension or denial of cellular telephone services to the offender, or legal action or both.

Some airlines may permit the use of cellular phones while the aircraft is on the ground and the door is open. The MC7750 modem may be used normally at this time.

Important compliance information for North American users

The MC7750 modem has been granted modular approval for mobile applications. Integrators may use the modem in their final products without additional FCC/IC (Industry Canada) certification if they meet the following conditions. Otherwise, additional FCC/IC approvals must be obtained.

- Although the MC7750 modem has been granted module approval, there are many conditions attached to this approval; final host integration will likely require additional testing. Detailed guidelines are described in OEM device classification process on page 61 to assist OEM module integrators in determining the extent of additional testing necessary to comply with FCC requirements.
- The end product with an embedded MC7750 modem must be evaluated for simultaneous transmission requirements. See Simultaneous transmission evaluation on page 62 for details.
- A user manual with the end product must clearly indicate the operating requirements and conditions that must be observed to ensure compliance with current FCC / IC RF exposure guidelines. See OEM product instruction manual content on page 63 for details.
- To comply with FCC / IC regulations limiting both maximum RF output power and human exposure to RF radiation, the maximum antenna gain including cable loss in a mobile-only exposure condition must not exceed:
 - · Part 22 (Cellular): 7.3 dBi
 - · Part 24 (PCS): 3 dBi
 - · Part 27 (Band 13): 9 dBi
- A label must be affixed to the outside of the end product into which the MC7750 modem is incorporated, with a statement similar to the following:
 - This device contains FCC ID: N7NMC7750
 This equipment contains equipment certified under IC: 2417C-MC7750

The end product with an embedded MC7750 modem may also need to pass the FCC Part 15 unintentional emission testing requirements and be properly authorized per FCC Part 15.

Note: If this module is intended for use in a portable device, you are responsible for separate approval to satisfy the SAR requirements of FCC Part 2.1093 and IC RSS-102.

OEM integration

Application of regulatory guidelines

Because 'near-body' devices (handhelds, laptops, tablets, scanners, etc.) vary widely in design features, physical configurations, and use-models, module integrators shall follow the guidelines below regarding device classification and simultaneous transmission, and seek guidance from their preferred regulatory test lab to determine how regulatory guidelines will impact the device compliance. Proactive management of the regulatory process will minimize unexpected schedule delays and costs due to unplanned testing activities.

Device classifications

The OEM integrator must determine the minimum distance required between their device and the user's body.

The FCC provides device classification definitions to assist in making the correct determination. Note that these classifications are guidelines only; strict adherence to a device classification may not satisfy the regulatory requirement as near-body device design details may vary widely.

FCC definitions:

Portable: (§2.1093)—A portable device is defined as a transmitting device designed to be used so that the radiating structure(s) of the device is/are within 20 centimeters of the body of the user.

Mobile: (§2.1091)(b)—A mobile device is defined as a transmitting device designed to be used in other than fixed locations and to generally be used in such a way that a separation distance of at least 20 centimeters is normally maintained between the transmitter's radiating structure(s) and the body of the user or nearby persons.

Per §2.1091d(d)(4) In some cases (for example, modular or desktop transmitters), the potential conditions of use of a device may not allow easy classification of that device as either Mobile or Portable. In these cases, applicants are responsible for determining minimum distances for compliance for the intended use and installation of the device based on evaluation of either specific absorption rate (SAR), field strength, or power density, whichever is most appropriate.

OEM device classification process

The primary factor in determining whether a device will be classified as a Portable product or as a Mobile product is antenna separation distance (body to radiating antenna element).

The review process between the OEM module integrator and the preferred regulatory test lab is a crucial step in determining the appropriate device classification, as it is impractical for Sierra Wireless to define all possible combinations of design features, antennas, physical configurations, and usemodels.

- 1. Perform a device review with the preferred regulatory test lab to confirm device classification.
- 2. Determine the Certification type (Standalone or C2PC from an existing Modular Grant).
- 3. If the device classification is:
 - Portable: Preferred regulatory test lab to determine if a PBA or KDB is required.
 - Mobile: Preferred regulatory test lab to determine if a PBA is required.
 (Note: A PBA or KDB will likely be required for new technologies such as LTE or WiMAX.)
- **4.** If the device classification is Mobile, confirm the antenna does not violate the Gain Limits specific to the module grant as specified in Important compliance information for North American users on page 60.
- 5. Outline and execute a test plan with the preferred regulatory test lab. Testing is likely to include some or all of Parts 15, 22, 24, 27, and either SAR (for Portable devices) or MPE (for Mobile devices).
- **6.** Follow product labeling requirements as described in Important compliance information for North American users on page 60. (Ref §2.925)
- 7. Include the OEM product instruction manual content on page 63 boilerplate text within the host product's instruction manual.

Simultaneous transmission evaluation

The MC7750 modem has **not** been evaluated or approved for simultaneous transmission as the number of possible multi-transmission scenarios for this device is large. Any simultaneous transmission condition established through module integration into a customer-specific product **must** be evaluated per the requirements in KDB447498D01(8) and KDB616217D01,D03 (for laptop, notebook, netbook, and tablet applications).

These requirements include, but are not limited to:

- Transmitters and modules certified for mobile or portable exposure conditions can be incorporated in mobile host devices without further testing or certification when:
 - The closest separation among all simultaneous transmitting antennas is ≥20 cm.

or

 Antenna separation distance and MPE compliance requirements for All simultaneous transmitting antennas have been specified in the application filing of at least one of the certified transmitters within the host device. In addition, when transmitters certified for portable use are incorporated in a mobile host device, the antenna(s) must be ≥5 cm from all other simultaneous transmitting antennas. All antennas in the final product must be at least 20 cm from users and nearby persons.

OEM product instruction manual content

Consistent with §2.909(a), the following text must be included within the user's manual or operator instruction guide for the final commercial product. (OEM-specific content is *displayed in italics*.)

Operating Requirements and Conditions

The design of (*Product Name*) complies with U.S. Federal Communications Commission (FCC) guidelines respecting safety levels of radio frequency (RF) exposure for (*OEM to insert device classification: Mobile or Portable*) devices.

FCC ID: (Include Standalone FCC ID or Module FCC ID as required)

Note: Include the following RF Exposure statement for Mobile devices only.

RF Exposure - This device is only authorized for use in a mobile application. At least 20 cm (8 inches) of separation distance between the (*Product Name*) device and the user's body must be maintained at all times.

Note: Include the following RF Exposure statement for Portable devices only.

RF Exposure - This device has been tested for compliance with FCC RF exposure limits in a portable configuration. At least (*Insert Required Separation Distance from RF Exposure Evaluation*) cm of separation distance between the (*Product Name*) device and the user's body must be maintained at all times. This device must not be used with any other antenna or transmitter that has not been approved to operate in conjunction with this device.

Note: Always include the following Caution statement.

CAUTION: Any changes or modifications not expressly approved by (*Company Name*) or Sierra Wireless could void the user's authority to operate the equipment.

Note: Include the following statement if Part 15 of the FCC Rules is required. Integration into host devices containing unlicensed devices may require additional comments in this section. The OEM should confirm the extent of their user's guide content with their preferred regulatory test lab.

Note: This equipment has been tested and found to comply with the limits for a (*OEM to insert device type: Class A or Class B*) digital device, pursuant to Part 15 of the FCC Rules. (*OEM must follow Part 15 guidelines* (§15.105 and §15.19) to determine additional statements required in this section for their device class)

>> A: Antenna Specification

This appendix describes recommended electrical performance criteria for main path, diversity path, and GPS antennas used with AirPrime embedded modules.

The performance specifications described in this section are valid while antennas are mounted in the host device with antenna feed cables routed in their final application configuration.

Note: Antennas should be designed **before** the industrial design is finished to make sure that the best antennas can be developed.

Table A-1: Antenna requirements ^a

Parameter	Requirements	Comments
Antenna system	External multi-band 2x2 MIMO antenna system (Ant1/Ant2) ^b	If Ant2 includes GPS, then it must also satisfy requirements in Table A-2 on page 67.
Operating bands of Ant1	700–960 MHz	
and Ant2	1710–1990 MHz	
	2110-2170 MHz	
	2500–2700 MHz	
VSWR of Ant1 and Ant2	1:1 (ideal) < 2.5:1 (recommended)	On all bands including band edges
Total radiated efficiency of Ant1 and Ant2	> 50% on all bands	Measured at the RF connector.
Anti anu Antz		 Includes mismatch losses, losses in the matching circuit, and antenna losses, excluding cable loss.
		Sierra Wireless recommends using antenna efficiency as the primary parameter for evaluating the antenna system. Peak gain is not a good indication of antenna performance when integrated with a host device (the antenna does not provide omni-directional gain patterns). Peak gain can be affected by antenna size, location, design type, etc.—the antenna gain patterns remain fixed unless one or more of these parameters change.
Radiation patterns of Ant1 and Ant2	Nominally Omni-directional radiation pattern in azimuth plane.	

Table A-1: Antenna requirements (Continued)^a

Parameter	Requirements	Comments			
Envelope correlation coefficient between Ant1	< 0.4 on 730–960 MHz band				
and Ant2	< 0.3 on 1800–1990 MHz and 2110–2170 MHz bands				
	< 0.2 on 2600–2700 MHz band				
Mean Effective Gain of Ant1 and Ant2 (MEG1, MEG2)	≥ -3 dBi				
Ant1 and Ant2 Mean Effective Gain Imbalance I MEG1 / MEG2 I	< 2 dB for MIMO operation < 6 dB for diversity operation				
Maximum antenna gain	Must not exceed antenna gains due to RF exposure and ERP/ EIRP limits, as listed in the module's FCC grant.	See Important compliance information for North American users on page 60.			
Isolation between Ant1 and Ant2 (S21)	> 10 dB	 If antennas can be moved, test all positions for both antennas. Make sure all other wireless devices (Bluetooth or WLAN antennas, etc.) are turned OFF to avoid interference. 			
Power handling	 > 2 W RF power on low bands > 1 W on high bands 	 Measure power endurance over 4 hours (estimated talk time) using a 2 W CW signal—set the CW test signal frequency to the middle of the PCS Tx band (1880 MHz for PCS). Visually inspect device to ensure there is no damage to the antenna structure and matching components. VSWR/TIS/TRP measurements taken before and after this test must show similar results. 			

a. These worst-case VSWR figures for the transmitter bands may not guarantee RSE levels to be within regulatory limits. The device alone meets all regulatory emissions limits when tested into a cabled (conducted) 50 ohm system. With antenna designs with up to 2.5:1 VSWR or worse, the radiated emissions could exceed limits. The antenna system may need to be tuned in order to meet the RSE limits as the complex match between the module and antenna can cause unwanted levels of emissions. Tuning may include antenna pattern changes, pahse/delay adjustment, passive component matching. Examples of the application test limits would be included in FCC Part 22 and Part 24, test case 12.2.1 for GSM (3GPP TS 51.010), and test case 4.2.2 for WCDMA (ETSI EN 301 511).

b. Ant1—Primary, Ant2—Secondary (Diversity/MIMO/GPS connector 2)

c. Stated band ranges satisfy requirements for both Ant1 and Ant2.

Recommended GPS antenna specifications

Table A-2: GPS standalone antenna requirements

Parameter	Requirements	Comments
Frequency range	 1575.42 MHz ±2 MHz minimum 1565–1606 MHz recommended 	
Field of view (FOV)	 Omni-directional in azimuth -45° to +90° in elevation 	
Polarization (average Gv/Gh)	> 0 dB	Vertical linear polarization is sufficient.
Free space average gain (Gv+Gh) over FOV	> -6 dBi (preferably > -3 dBi)	Gv and Gh are measured and averaged over -45° to +90° in elevation, and ±180° in azimuth.
Gain	 Maximum gain and uniform coverage in the high elevation angle and zenith. Gain in azimuth plane is not desired. 	
Average 3D gain	> -5 dBi	
Isolation between GPS and Ant1	> 10 dB in all uplink bands	
Typical VSWR	< 2.5:1	
Polarization	Any other than LHCP (left-hand circular polarized) is acceptable.	

Antenna tests

The following guidelines apply to the requirements described in Table A-1 on page 65 and Table A-2 on page 67:

- Perform electrical measurements at room temperature (+20°C to +26°C) unless otherwise specified
- For main and diversity path antennas, make sure the antennas (including contact device, coaxial cable, connectors, and matching circuit with no more than six components, if required) have nominal impedances of 50 Ω across supported frequency bands.
- All tests (except isolation/correlation coefficient)—Test the main or diversity antenna with the other antenna terminated.

- Any metallic part of the antenna system that is exposed to the outside environment needs to meet the electrostatic discharge tests per IEC61000-4-2 (conducted discharge +8kV).
- The functional requirements of the antenna system are tested and verified while the embedded module's antenna is integrated in the host device.

Note: Additional testing, including active performance tests, mechanical, and accelerated life tests can be discussed with Sierra Wireless' engineering services. Contact your Sierra Wireless representative for assistance.



This chapter provides a summary of the design considerations mentioned throughout this guide. This includes items relating to the power interface, RF integration, thermal considerations, cabling issues, and so on.

Note: This is NOT an exhaustive list of design considerations. It is expected that you will employ good design practices and engineering principles in your integration.

Table B-1: Hardware integration design considerations

Suggestion	Section where discussed
Component placement	
Protect the SIM socket so the SIM cannot be removed while the host is powered up.	SIM implementation on page 32
If an ESD suppressor is not used, allow space on the SIM connector for series resistors in layout. (Up to 100 Ω may be used depending on ESD testing requirements).	SIM implementation on page 32
Minimize RF cable losses as these affect performance values listed in product specification documents.	RF connections on page 37
Antennas	,
Match the module/antenna coax connections to 50 Ω — mismatched antenna impedance and cable loss negatively affect RF performance.	RF connections on page 37
If installing CDMA and UMTS modules in the same device, consider using separate antennas for maximum performance.	Antenna and cabling on page 38
Power	
Make sure the power supply can handle the maximum current specified for the module type.	Power consumption on page 45
Limit the total impedance of VCC and GND connections to the SIM at the connector to less than 1 Ω (including any trace impedance and lumped element components—inductors, filters, etc.). All other lines must have a trace impedance less than 2 Ω .	SIM implementation on page 32
Decouple the VCC line close to the SIM socket. The longer the trace length (impedance) from socket to module, the greater the capacitance requirement to meet compliance tests.	SIM implementation on page 32
EMI/ESD	,
Investigate sources of localized interference early in the design cycle.	Methods to mitigate decreased Rx performance on page 40

Table B-1: Hardware integration design considerations (Continued)

Suggestion	Section where discussed
Provide ESD protection for the SIM connector at the exposed contact point (in particular, the CLK, VCC, IO, and RESET lines).	SIM implementation on page 32
Keep very low capacitance traces on the USIM_DATA and USIM_CLK signals.	SIM implementation on page 32
To minimize noise leakage, establish a very good ground connection between the module and host.	Ground connection on page 39
Route cables away from noise sources (for example, power supplies, LCD assemblies, etc.).	Methods to mitigate decreased Rx performance on page 40
Shield high RF-emitting components of the host device (for example, main processor, parallel bus, etc.).	Methods to mitigate decreased Rx performance on page 40
Use discrete filtering on low frequency lines to filter out unwanted high-order harmonic energy.	Methods to mitigate decreased Rx performance on page 40
Use multi-layer PCBs to form shielding layers around high-speed clock traces.	Methods to mitigate decreased Rx performance on page 40
Thermal	
Test to worst case operating conditions—temperature, voltage, and operation mode (transmitter on 100% duty cycle, maximum power).	Thermal considerations on page 56
Use appropriate techniques to reduce module temperatures (for example, airflow, heat sinks, heat-relief tape, module placement, etc.).	Thermal considerations on page 56
Host/Modem communication	
Make sure the host USB driver supports remote wakeup, resume, and suspend operations, and serial port emulation.	[5] AirCard/AirPrime USB Driver Developer's Guide (Doc# 2130634)
When no valid data is being sent, do not send SOF tokens from the host (causes unnecessary power consumption).	[5] AirCard/AirPrime USB Driver Developer's Guide (Doc# 2130634)

Note: All AirPrime embedded modules are factory-tested to ensure they conform to published product specifications.

Developers of OEM devices integrating Sierra Wireless AirPrime embedded modules should include a series of test phases in their manufacturing process to make sure that *their* devices work properly with the embedded modules.

Suggested phases include:

- Acceptance testing—Testing of modules when they are received from Sierra Wireless
- Certification testing—Testing of completed devices to obtain required certifications before beginning mass production
- Production testing—Testing of completed devices with the modules embedded
- Quality assurance testing—Post-production

AT command entry timing requirement

Some AT commands require time to process before additional commands are entered. For example, the modem will return "OK" when it receives AT!DAFTMACT. However, if AT!DASBAND is received too soon after this, the modem will return an error.

When building automated test scripts, ensure that sufficient delays are embedded where necessary to avoid these errors.

Acceptance testing

Note: Acceptance testing is typically performed for **each** shipment received.

When you receive a shipment from Sierra Wireless, you should make sure it is suitable before beginning production.

From a random sampling of units, test that:

- Units are operational
- Units are loaded with the correct firmware version

Acceptance test requirements

To perform the suggested tests, you require a test system in which to temporarily install the module, and you must be able to observe the test device's LED indicator.

Acceptance test procedure

The following is a suggested acceptance testing procedure using Sierra Wireless' Watcher™ software:

Note: You can perform these tests using appropriate AT commands.

Test 1: Check power-up and initialization

- **1.** After installing the module, start the test system.
- 2. Launch Watcher.
- 3. Check the LED—If the LED is off, there is a problem with the module or with the connection to the LED.

Test 2: Check version numbers

- 1. From Watcher, select Help > About.
- 2. Verify that the firmware version in the About window is correct.
- 3. Close the About window.

If the module fails either of these tests, or is not recognized by Watcher:

- 1. Replace the module with one that is known to work correctly and repeat the tests.
- 2. If the tests are successful, reinstall the original module and repeat the tests.

If the module still does not work correctly, contact your account manager.

Certification testing

Note: Typically, certification testing of your device with the integrated module is required one time only.

The AirPrime embedded module has been certified as described in Regulatory and Industry Approvals on page 59.

When you produce a host device with a Sierra Wireless AirPrime embedded module, you must obtain certifications for the final product from appropriate regulatory bodies in the jurisdictions where it will be distributed.

The following are *some* of the regulatory bodies from which you may require certification—it is your responsibility to make sure that you obtain all necessary certifications for your product from these or other groups:

- FCC (Federal Communications Commission—www.fcc.gov)
- Industry Canada (www.ic.gc.ca)
- CSA (Canadian Standards Association—www.csa.ca)

- Factory Mutual (FM Global—www.allendale.com)
- Underwriters Laboratories Inc. (www.ul.com)
- CDG (CDMA Development Group—www.cdg.org)
- GCF (Global Certification Forum—www.globalcertificationforum.org) outside of North America
- PTCRB (PCS Type Certification Review Board—www.ptcrb.com) in North America

Production testing

Note: Production testing typically continues for the life of the product.

Production testing ensures that, for each assembled device, the module is installed correctly (I/O signals are passed between the host and module), and the antenna is connected and performing to specifications (RF tests).

Typical items to test include:

- Host connectivity
- Baseband (GPIO, host/module connectors)
- RF assembly (Tx and/or Rx, as appropriate)
- Network availability
- Host/device configuration issues

Note: The amount and types of tests to perform are **your** decision—the tests listed in this section are guidelines only. Make sure that the tests you perform exercise functionality to the degree that **your** situation requires.

Use an appropriate test station for your testing environment (see Acceptance test requirements on page 72 for suggestions) and use AT commands to control the integrated module.

Note: Your test location must be protected from ESD to avoid interference with the module and antenna(s), assuming that your test computer is in a disassembled state.

Also, consider using an RF shielding box—local government regulations may prohibit unauthorized transmissions.

Functional production test

This section presents a suggested procedure for performing a basic manual functional test on a laboratory bench using an AirPrime embedded module and a Mini Card Dev Kit. When you have become familiar with the testing method, use it to develop your own automated production testing procedures.

Suggested production tests

Consider the following tests when you design your production test procedures for devices with the AirPrime module installed.

- Visual check of the module's connectors and RF assemblies
- Module is operational
- USB connection is functional
- LED is functional
- W_DISABLE_N (module power down)
- Firmware revision check
- Rx tests on main and auxiliary paths
- Tx test

Production test procedure

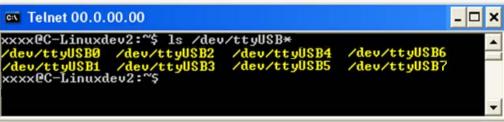
The following is a suggested test plan—you must decide which tests are appropriate for your product. You may wish to add additional tests that more fully exercise the capabilities of your product.

Using an appropriate Dev Kit-based test station, and referring to the appropriate AT command references:

- 1. Visually inspect the module's connectors and RF assemblies for obvious defects before installing it in the test station.
- 2. Ensure that the module is turned off before beginning your tests—Drive W_DISABLE_N low.
- **3.** If using Linux, determine if any USB devices are currently connected to the computer:
 - a. Open a shell window and enter the command Is /dev/tty/USB*.
 - **b.** Record the ttyUSB*n* values that are returned; these are the currently connected USB devices. If the command returns "no such file or directory", there are no devices currently connected.
- **4.** Test W_DISABLE_N—Turn on the module by letting W_DISABLE_N float (high impedance).
- 5. Test USB functionality—Check for USB enumeration.
 - (Windows systems) The Device Manager shows Sierra Wireless items under Ports (COM & LPT). The devices shown depend on the module type. For example:]



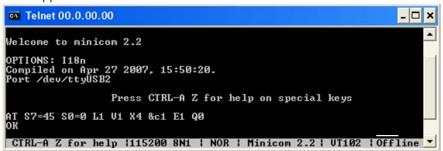
 (Linux systems) Enter the command Is /dev/tty/USB* and then record and compare the results with those from Step 3. If there are any new ttyUSBn devices, then the modem has enumerated successfully. (There should be seven new devices) For example: With one other USB device already connected and assigned to ttyUSB1:



(Note: The AT port is the fourth new device—/dev/ttyUSB4.)

- **6.** Make sure your modem is connected and running, and then establish contact with the module:
 - Windows systems: Use a terminal emulation/communications program such as Microsoft HyperTerminal[®] to connect over the COM port reserved for AT commands (see listings in Step 5):
 - a. Start HyperTerminal.
 - **b.** Select **File > Connection Description**. The Connection Description dialog box appears.
 - i. Type Sierra in the Name box and click **OK**. The Connect To dialog box appears.
 - **ii.** Click **OK** without changing any of the displayed information. The Connect dialog box appears.
 - iii. Click Cancel.
 - **iv.** Type ATZ in the HyperTerminal window. If the connection is established, the message OK appears.
 - Linux systems: Use a terminal emulation/communications program such as minicom to connect over the device handle for AT commands (see listings in Step 5):
 - i. Start minicom:
 - First use of the modem: From the command line, type minicom -s. (The '-s' switch shows the configuration menu.)
 - Subsequent uses: From the command line, type minicom. (The '-s' switch is assumed.)

The minicom configuration details appear and the message OK appears when the connection is established.



Note: If necessary, use *ATE1* to enable echo.

Note: If the command "minicom" is not found, then use a different program, or download minicom and repeat this step. See Downloading and configuring minicom for Linux systems on page 76 for details.

- 7. Display the firmware version:
 - · AT!GVER
- **8.** Test the LED—Set the LED in blinking mode using this command, then visually verify that the LED turns off and on:
 - · AT!LEDCTRL
- 9. Unlock the extended AT command set:
 - · AT!ENTERCND
- **10.** Put the module in diagnostic/factory test mode:
 - AT!DAFTMACT
- **11.** Communicate with the SIM using **+CPIN** or **+CIMI**. When performing RF tests, use a test platform as described in Suggested testing equipment on page 81.
- 12. Test RF transmission, if desired:
 - (LTE) To test the LTE transmission path, use a call box.
- 13. Test RF reception, if desired:
 - (CDMA) See Testing CDMA RF Receive path on page 77.
 - (LTE) See LTE RF receive path test on page 78.
- **14.** Test standalone GPS functionality—See GPS standalone connector test on page 80.
- **15.** Drive W_DISABLE_N low and confirm that the module powers down:
 - Windows systems—The Sierra Wireless items under the Ports (COM & LPT) entry in Device Manager disappear as the module powers off.
 - Linux systems—Enter the command Is /dev/tty/USB*. The devices enumerated in Step 5 will not appear after the module powers off.

Downloading and configuring minicom for Linux systems

Note: This procedure is for Ubuntu systems. If you are using a different Linux distribution, use the appropriate commands for your system to download minicom.

To download and configure minicom in a Ubuntu system:

- 1. Download and install minicom—enter the following command: sudo apt-get install minicom
- **2.** When prompted, enter your user password to begin the download and installation. When minicom is installed, the shell prompt appears.
- 3. Configure minicom to communicate with your modem:
 - a. Start minicom with the following command: minicom -s
- 4. Use the down-arrow key to select the Serial port setup option.
- **5.** Refer to Step 5 on page 74 to identify the device file handle (/dev/ttyUSBn) used for AT commands.
- 6. Indicate the file handle to use for AT commands—Enter A and then replace the serial device string with the AT file handle (for example, /dev/ttyUSB4 as shown in the example in Step 5 on page 74).
- **7.** Press Enter twice.

Note: To install minicom, you must have root access, or be included in the sudoers list.

- 8. Use the down-arrow key to select Save setup as dfl.
- 9. Select Exit.

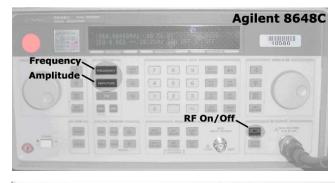
Testing CDMA RF Receive path

Note: This procedure segment is performed in Step 13 of the Production test procedure on page 74.

To test the DUT's receive path:

1. Set up the signal generator:

Note: This procedure describes steps using the Agilent 8648C signal generator—the Rohde & Schwarz SML03 is shown for reference only.





a. Press the **Frequency** button to set the frequency to 1960.200 MHz for PCS band, Channel 600, or 881.720 MHz for Cellular band, Channel 384

- b. Press the Amplitude button to set the amplitude to -55.0 dBm.
- **c.** Press the **RF ON/OFF** button to enable or disable the RF port of the signal generator.
- 2. Read back the power level from the main receiver:
 - **a.** AT!ENTERCND (Unlock the extended AT command set.)
 - **b.** AT!DAFTMACT (Enter test mode.)
 - **c.** AT!CHAN=600,1 (PCS band, channel 600) *or*

AT!CHAN=384,0 (Cellular band, channel 384)

- **d.** AT!RX=1 (Turn on the main receiver.)
- **e.** AT!RXAGC? (Read back the power level, in dBm, from the main receiver.) Response examples:
 - RXAGC = 0xFFFFFF33 = -77 dBm (Signal generator's RF port is OFF)
 - RXAGC = 0x0021 = -60 dBm typical (Signal generator's RF port is ON)

Note: This example setup uses a 200 kHz offset from band center for testing using a continuous wave—you can use any appropriate baseband frequency offset (for example, 100 kHz, 300 kHz, etc.).

If using a modulated signal, set the frequency to band center with no offset.

Note: The dBm value displayed is calculated to reflect the power at the input connector.

- f. AT!RX2=1 (Turn on diversity receiver.)
- **g.** AT!RX2AGC? (Read back the power level, in dBm, from the diversity receiver.)

Response examples:

- RX2AGC = 0xFFFFFF76 = -84 dBm (Signal generator's RF port is OFF)
- RX2AGC = 0xFFFFFC6 = -69 dBm typical (Signal generator's RF port is ON)
- **h.** AT!RX=0 (Turn off main receiver.)
- i. AT!RX2=0 (Turn off diversity receiver.)
- **3.** Test limits—Run ten or more good DUTs through this test procedure to obtain a nominal received power value.
 - Apply a tolerance of ± 5 to 6 dB to each measurement (assuming a good setup design).
 - Make sure the measurement is made at a high enough level that it is not influenced by DUT-generated and ambient noise.
 - · The Signal Generator power level should be at least -50 dBm.
 - Monitor these limits during mass-production ramp-up to determine if further adjustments are needed.

Note: The value measured by the DUT depends on the test setup and DUT design. Host RF cabling loss, antenna efficiency and pattern, test antenna efficiency and pattern, and choice of shield box all significantly influence the measurement.

Note: When doing the same test over the air in an RF chamber, values are likely to be significantly lower.

LTE RF receive path test

Note: This procedure segment is performed in Step 13 of the Production test procedure on page 74.

Table C-1 contains parameters used in the suggested test procedure that follows.

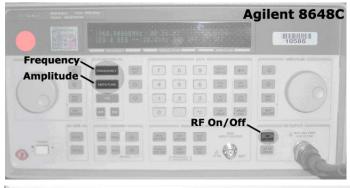
Table C-1: Test settings—Receive path

Mode	Test category	Bands		
		B13	B17	B4
LTE	Frequency ^a (MHz)	753.0	742.0	2134.5
	Band	36	37	42
	Channel ^b	23230	23790	20175

- a. All values offset from actual center channel by +2 MHz
- b. Channel values shown are at the center of the corresponding bands.

To test the DUT's receive path (or diversity path, while connected to the diversity antenna):

Note: This procedure describes steps using the Agilent 8648C signal generator—the Rohde & Schwarz SML03 is shown for reference only. 1. Set up the signal generator:





- a. Set the amplitude to -70 dBm
- **b.** Set the frequency for the band being tested. See Table C-1 for frequency values.
- **2.** Set up the DUT:
 - **a.** AT!ENTERCND (Unlock extended AT command set.)
 - **b.** AT!DAFTMACT (Put modem into factory test mode.)
 - **c.** AT!DASBAND=<band> (Set frequency band.)
 - See Table C-1 on page 78 for <band> values
 - **d.** AT!DASCHAN=<channel> (Set modem channel)
 - See Table C-1 on page 78 for <channel> values
 - e. AT!DALGAVGAGC=<channel>,0 (Get averaged Rx AGC)
 - See Table C-1 on page 78 for <channel> values
- **3.** Test limits—Run ten or more good DUTs through this test procedure to obtain a nominal received power value.
 - Apply a tolerance of ± 5 to 6 dB to each measurement (assuming a good setup design).
 - Make sure the measurement is made at a high enough level that it is not influenced by DUT-generated and ambient noise.
 - The Signal Generator power level can be adjusted and new limits found if the radiated test needs greater signal strength.
 - Monitor these limits during mass-production ramp-up to determine if further adjustments are needed.

Note: The value measured from the DUT is significantly influenced by the test setup and DUT design (host RF cabling loss, antenna efficiency and pattern, test antenna efficiency and pattern, and choice of shield box).

GPS standalone connector test

GPS testing should be done on devices that support a dedicated GPS connector.

If the MC7750 supports a dedicated GPS connector/path (that is, not shared with the diversity connector), then GPS testing may be done by characterizing some known-good MC devices and checking for carrier to noise levels.

To test the GPS path:

- 1. Inject a carrier signal at -110dBm, frequency 1575.52 MHz into the GPS Rx path. (Note that this is 100kHz higher than the actual GPS frequency.)
- 2. Test the signal carrier-to-noise level at the GPS receiver:
 - **a.** AT!ENTERCND (Unlock extended AT command set.)
 - **b.** AT!DAFTMACT (Put modem into factory test mode.)
 - **c.** AT!DACGPSTESTMODE=1 (Start CGPS diagnostic task.)
 - **d.** AT!DACGPSSTANDALONE=1 (Enter standalone RF mode.)
 - e. AT!DACGPSMASKON (Enable log mask.)
 - f. AT!DACGPSCTON (Return signal-to-noise and frequency measurements.)
 - **g.** Repeat AT!DACGPSCTON five to ten times to ensure the measurements are repeatable and stable.
- **3.** Leave the RF connection to the Mini Card device intact, and turn off the signal generator.
- 4. Take several more !DACGPSCTON readings. This will demonstrate a 'bad' signal in order to set limits for testing, if needed. This frequency offset should fall outside of the guidelines in the note below, which indicates that the CtoN result is invalid.
- **5.** (Optional) Turn the signal generator on again, and reduce the level to 120dBm. Take more !DACGPSCTON readings and use these as a reference for what a marginal/poor signal would be.

Note: The response to AT!DACGPSCTON for a good connection should show CtoN within 58 +/- 5dB and Freq (frequency offset) within 100000 Hz +/- 5000 Hz.

Quality assurance testing

Note: QA is an ongoing process based on random samples from a finished batch of devices.

The quality assurance tests that you perform on your finished products should be designed to verify the performance and quality of your devices.

The following are *some* testing suggestions that can confirm that the antenna is interfaced properly, and that the RF module is calibrated and performs to specifications:

Module registration on cellular networks

- Power consumption
- Originate and terminate data and voice (if applicable) calls
- Cell hand-off
- Transmitter and receiver tests
- FER (Frame Error Rate) as an indicator of receiver sensitivity/performance
- Channel and average power measurements to verify that the device is transmitting within product specifications
- RF sensitivity tests
- CDMA:
 - FER testing—Test receiver sensitivity for conditions of minimum cell power. FER can be measured for the specified receiver sensitivity of -104 dBm. The objective of this test is to determine if the FER measured is within the acceptable limits for the specified receiver sensitivity of the module. Unlike the FER tests performed during production testing, this test determines the receiver performance without the influence of the noise factor (AWGN), but with extremely low cell power. The reported FER and the confidence level must be <1% and >95% respectively for the test to be considered a pass.

Suggested testing equipment

To perform production and post-production tests, you will require appropriate testing equipment. A test computer can be used to coordinate testing between the integrated module (on the development kit or host) and the measurement equipment, usually with GPIB connections. The suggested setup includes a power meter to test RF output power and a signal generator to evaluate the receiver.

Testing assistance provided by Sierra Wireless

Extended AT commands have been implemented to assist with performing FTA GCF tests and portions of CE Mark tests requiring radio module access. These are documented in the [2] AirCard/AirPrime UMTS Devices Supported AT Command Reference (Doc# 2130617) and [3] AirPrime MC8xxx Embedded Modules Extended AT Command Reference (Doc# 2130616).

Sierra Wireless offers optional professional services based assistance to OEMs with regulatory approvals.

IOT/Operator testing

Interoperability and Operator/Carrier testing of the finished system is the responsibility of the OEM. The test process will be determined with the chosen network operator(s) and will be dependent upon your business relationship with them, as well as the product's application and sales channel strategy.

Sierra Wireless offers assistance to OEMs with the testing process, if required.

Extended AT commands for testing

Sierra Wireless provides proprietary AT commands that may help in hardware integration design and testing (these commands are NOT intended for use by end users):

- [3] AirPrime MC8xxx Embedded Modules Extended AT Command Reference (Doc# 2130616)
- [2] AirCard/AirPrime UMTS Devices Supported AT Command Reference (Doc# 2130617)

Some useful commands from these documents for use in hardware integration are listed in Table C-2 on page 82.

Table C-2: Extended AT commands

Command	Description
Password commands	
!ENTERCND	Enable access to password-protected commands
!SETCND	Set AT command password
Modem reset and statu	s commands
!GRESET	Reset the modem
!GSTATUS	Return the operation status of the modem (mode, band, channel, and so on)
Diagnostic commands	
!BAND	Select a set of frequency bands or reports current selection
!GBAND	Read/set the current operating band
Test commands	
!ALLUP	Turn transmitter on/off and simulate 'All UPs'
!CHAN	Tune synthesizer to channel/band
!DAFTMACT	Put the modem into FTM (Factory Test Mode)
!DAFTMDEACT	Put the modem into online mode
!DAGGRSSI	Return the RSSI (Received Signal Strength Indicator) in dBm (GSM mode)
!DAGGAVGRSSI	Return an averaged RSSI (Received Signal Strength Indicator) in dBm (GSM mode)
!DAGGRSSIRAW	Return the raw RSSI (GSM mode)
!DAGINFO	Return GSM mode RF information
!DAGSLOCK	Return the RF synthesizer lock state
!DAGSRXBURST	Set the GSM receiver to burst mode
!DAGSRXCONT	Set the GSM receiver continually on

Table C-2: Extended AT commands (Continued)

Command	Description
!DAGSTXBURST	Set the GSM transmitter to burst mode
!DAGSTXFRAME	Set the GSM Tx frame structure
!DALGAVGAGC	Return averaged Rx AGC value (LTE)
!DALGRXAGC	Return Rx AGC value (LTE)
!DALGTXAGC	Return Tx AGC value and transmitter parameters (LTE)
!DAOFFLINE	Place modem offline
!DASBAND	Set the frequency band (UMTS/GSM)
!DASCHAN	Set the modem channel (frequency) (UMTS/GSM)
!DASLNAGAIN	Set the LNA (Low Noise Amplifier) gain state
!DASPDM	Set the PDM (Pulse Duration Modulation) value
!DASTXOFF	Turn off the Tx PA (Power Amplifier)
!DASTXON	Turn on the Tx PA (Power Amplifier)
!DAWGAVGAGC	Return averaged RX AGC value (WCDMA)
!DAWGRXAGC	Return the Rx AGC (Automatic Gain Control) value (UMTS)
!DAWINFO	Return WCDMA mode RF information
!DAWSCONFIGRX	Set the UMTS receiver to factory calibration settings
!DAWSPARANGE	Set the PA range state machine (UMTS)
!DAWSCHAINTCM	Place receive chain in test call mode (WCDMA)
!DAWSSCHAIN	Enable secondary receive chain (WCDMA)
!DAWSTXCW	Set the waveform used by the transmitter (UMTS)
!DAWSTXPWR	Set desired Tx power level (WCDMA)
!IMSTESTMODE	Enable/disable IMS test mode
!KEYOFF	Key off the transmitter
!KEYON	Key on the transmitter
!OSDSM	Display memory usage for DSM (Distributed Shared Memory) buffer pools
\$QCAGC	Read Rx AGC (CDMA/WCDMA)
!RX2	Turn second receiver on/off
!RX2AGC	Read second receiver Rx AGC
!RXAGC	Read first receiver Rx AGC

Table C-2: Extended AT commands (Continued)

Command	Description
!TX	Turn transmitter on/off
!TXAGC	Set desired Tx AGC

>> D: Packaging

Sierra Wireless AirPrime Mini Cards are shipped in sealed boxes. The standard packaging (see Figure 4-1), contains a single tray with a capacity of 100 modules. (Note that some SKUs may have custom packaging—contact Sierra Wireless for SKU-specific details.)

In the standard packaging, Mini Cards are inserted, system connector first, into the bottom portion (T1) of a two-part tray. all facing the same direction. This allows the top edge of each Mini Card to contact the top of the triangular features in the top portion (T2) of the tray (see Detail A).

The top and bottom portions of the tray snap together at the four connection points.

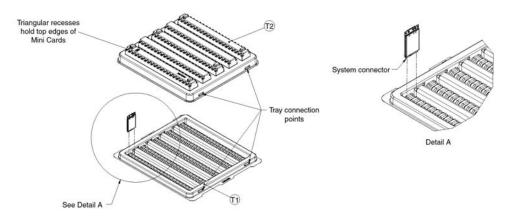


Figure 4-1: Device placement in module tray

The tray is placed in a manufacturing box (T2 at the top), sealed with a security tape (P1), and a manufacturing label is placed on the bottom-right corner, above the security tape. (See Figure 4-2.)

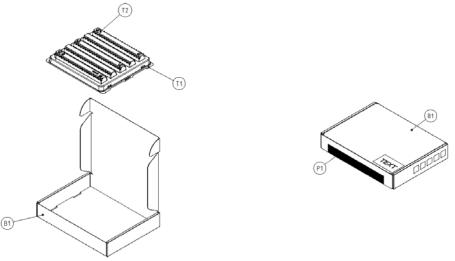


Figure 4-2: Shipping package

E: References

This guide deals specifically with hardware integration issues that are unique to AirPrime embedded modules.

Web site support

For additional documents describing embedded module design, usage, and integration issues (AT command references, integration guides, etc.), visit www.sierrawireless.com/minicard. To obtain access permission, contact your Sierra Wireless account representative.

Sierra Wireless documents

The following Sierra Wireless documents are available from www.sierrawireless.com.

Command documents

- [1] AT Command Set for User Equipment (UE) (Release 6) (Doc# 3GPP TS 27.007)
- [2] AirCard/AirPrime UMTS Devices Supported AT Command Reference (Doc# 2130617)
- [3] AirPrime MC8xxx Embedded Modules Extended AT Command Reference (Doc# 2130616)

Other Sierra documents

- [4] PCI Express Mini Card Dev Kit Quick Start Guide (Doc# 2130705)
- [5] AirCard/AirPrime USB Driver Developer's Guide (Doc# 2130634)

Industry/other documents

The following non-Sierra Wireless references are not included in your documentation package:

- [6] CDMA 1x Standard (CDMA 200 Series Release A (2000)) (Doc# TIA/EIA/IS-2000 Series, Release A)
- [7] FCC Regulations Part 15 Radio Frequency Devices
- [8] IEC-61000-4-2 level 3
- [9] IEC-61000-4-2 level (Electrostatic Discharge Immunity Test)
- [10]Mobile Station (MS) Conformance Specification; Part 4: Subscriber Interface Module (Doc# 3GPP TS 11.10-4)

[11] PCI Express Mini Card Electromechanical Specification Revision 1.2

[12] Universal Serial Bus Specification, Rev 2.0

[13] JESD22-A114-B

[14] JESD22-C101

>>>|F: Acronyms

Table F-1: Acronyms and definitions

Acronym or term	Definition
1xEV-DO	Single Carrier (1X) EVolution – Data Only. A high-speed standard for cellular packet data communications. Supports Internet connections with data rates up to 3.1 Mbps (downlink from the network) and 1.8 Mbps (uplink to the network). Average data rates are roughly: for Rev. A: 600 1300 kbps (downlink from the network) and 300 400 kbps (uplink to the network); for Rev. 0: 400 700 kbps (downlink from the network) and 40 80 kbps (uplink to the network). Actual speed depends on the network conditions. Compare to 1X.
1X	Single Carrier (1X) Radio Transmission Technology. A high-speed standard for cellular packet data communications. Supports Internet connections with data rates up to 153 kbps (simultaneously in each direction—downlink and uplink). Actual speed depends on the network conditions. Compare to 1xEV-DO.
3GPP	3rd Generation Partnership Project
8PSK	Octagonal Phase Shift Keying
AGC	Automatic Gain Control
API	Application Programming Interface
BER	Bit Error Rate—A measure of receive sensitivity
BLER	Block Error Rate
bluetooth	Wireless protocol for data exchange over short distances
CAIT	CDMA Air Interface Tool
CDG	CDMA Development Group—a consortium of companies that develop and promote the products and services for CDMA wireless systems.
CDMA	Code Division Multiple Access. A wideband spread spectrum technique used in digital cellular, personal communications services, and other wireless networks. Wide channels (1.25 MHz) are obtained through spread spectrum transmissions, thus allowing many active users to share the same channel. Each user is assigned a unique digital code, which differentiates the individual conversations on the same channel.
CQI	Channel Quality Indication
COM	Communication port
cs	Circuit-switched
CSA	Canadian Standards Association
CW	Continuous waveform

Table F-1: Acronyms and definitions (Continued)

Acronym or term	Definition
dB	Decibel = 10 x log ₁₀ (P1/P2) P1 is calculated power; P2 is reference power
	Decibel = 20 x log ₁₀ (V1/V2) V1 is calculated voltage, V2 is reference voltage
dBm	A logarithmic (base 10) measure of relative power (dB for decibels); relative to milliwatts (m). A dBm value will be 30 units (1000 times) larger (less negative) than a dBW value, because of the difference in scale (milliwatts vs. watts).
DCS	Digital Cellular System A cellular communication infrastructure that uses the 1.8 GHz radio spectrum.
DL	Downlink (network to mobile)
DRX	Discontinuous Reception
DSM	Distributed Shared Memory
DUT	Device Under Test
EDGE	Enhanced Data rates for GSM Evolution
eHRPD	Evolved High Rate Packet Data—Enhances traditional 1xEV-DO to enable LTE to CDMA handover.
EIRP	Effective (or Equivalent) Isotropic Radiated Power
EMC	Electromagnetic Compatibility
ЕМІ	Electromagnetic Interference
ERP	Effective Radiated Power
ESD	Electrostatic Discharge
FCC	Federal Communications Commission The U.S. federal agency that is responsible for interstate and foreign communications. The FCC regulates commercial and private radio spectrum management, sets rates for communications services, determines standards for equipment, and controls broadcast licensing. Consult www.fcc.gov.
FDMA	Frequency Division Multiple Access
FER	Frame Error Rate—A measure of receive sensitivity.
firmware	Software stored in ROM or EEPROM; essential programs that remain even when the system is turned off. Firmware is easier to change than hardware but more permanent than software stored on disk.
FOTA	Firmware Over The Air—Technology used to download firmware upgrades directly from the service provider, over the air.
FOV	Field Of View
FSN	Factory Serial Number—A unique serial number assigned to the mini card during manufacturing.
GCF	Global Certification Forum

Table F-1: Acronyms and definitions (Continued)

Acronym or term	Definition
GLONASS	Global Navigation Satellite System
GMSK	Gaussian Minimum Shift Keying modulation
GND	Ground
GPRS	General Packet Radio Service
GPS	Global Positioning System A system that uses a series of 24 geosynchronous satellites to provide navigational data.
GSM	Global System for Mobile Communications
Host	The device into which an embedded module is integrated
Hz	Hertz = 1 cycle/second
IC	Industry Canada
IF	Intermediate Frequency
IMEI	International Mobile Equipment Identity
IMS	IP Multimedia Subsystem—Architectural framework for delivering IP multimedia services. (MC7750 supports MO/MT SMS over IMS for LTE/eHRPD.)
inrush current	Peak current drawn when a device is connected or powered on
inter-RAT	Radio Access Technology
ЮТ	Interoperability Testing
IS	Interim Standard. After receiving industry consensus, the TIA forwards the standard to ANSI for approval.
IS-2000	3G radio standards for voice and data (CDMA only)
IS-95	2G radio standards targeted for voice (cdmaONE)
LED	Light Emitting Diode. A semiconductor diode that emits visible or infrared light.
LHCP	Left-Hand Circular Polarized
LNA	Low Noise Amplifier
LPM	Low Power Mode
LPT	Line Print Terminal
LTE	Long Term Evolution—a high-performance air interface for cellular mobile communication systems.
MCS	Modulation and Coding Scheme
MHz	Megahertz = 10e6 Hz

Table F-1: Acronyms and definitions (Continued)

Acronym or term	Definition
MEID	Mobile Equipment Identifier—The unique second-generation serial number assigned to the minicard for use on the wireless network.
МІМО	Multiple Input Multiple Output—wireless antenna technology that uses multiple antennas at both transmitter and receiver side. This improves performance.
NAS/AS	Network Access Server
NC	No Connect
NDIS	Network Driver Interface SpecificationSpecification—a programming interface specification for connecting network interface cards in Windows.
NIC	Network Interface Card
NMEA	National Marine Electronics Association
OEM	Original Equipment Manufacturer—a company that manufactures a product and sells it to a reseller.
OFDMA	Orthogonal Frequency Division Multiple Access
OMA DM	Open Mobile Alliance Device Management—A device management protocol.
ОТА	'Over the air' (or radiated through the antenna)
PA	Power Amplifier
packet	A short, fixed-length block of data, including a header, that is transmitted as a unit in a communications network.
РСВ	Printed Circuit Board
PCS	Personal Communication System A cellular communication infrastructure that uses the 1.9 GHz radio spectrum.
PDN	Packet Data Network
PMI	Pre-coding Matrix Index
PSS	Primary synchronisation signal
PST	Product Support Tools
PTCRB	PCS Type Certification Review Board
QAM	Quadrature Amplitude Modulation. This form of modulation uses amplitude, frequency, and phase to transfer data on the carrier wave.
QMI	Qualcomm MSM/Modem Interface
QOS	Quality of Service
QPSK	Quadrature Phase-Shift Keying
QPST	Qualcomm Product Support Tools
RAT	Radio Access Technology

Table F-1: Acronyms and definitions (Continued)

Acronym or term	Definition
RF	Radio Frequency
RI	Ring Indicator
roaming	A cellular subscriber is in an area where service is obtained from a cellular service provider that is not the subscriber's provider.
RSE	Radiated Spurious Emissions
RSSI	Received Signal Strength Indication
SDK	Software Development Kit
SED	Smart Error Detection
Sensitivity (Audio)	Measure of lowest power signal that the receiver can measure.
Sensitivity (RF)	Measure of lowest power signal at the receiver input that can provide a prescribed BER/BLER/SNR value at the receiver output.
SIB	System Information Block
SIM	Subscriber Identity Module. Also referred to as USIM or UICC.
SIMO	Single Input Multiple Output—smart antenna technology that uses a single antenna at the transmitter side and multiple antennas at the receiver side. This improves performance and security.
SISO	Single Input Single Output—antenna technology that uses a single antenna at both the transmitter side and the receiver side.
SKU	Stock Keeping Unit—identifies an inventory item: a unique code, consisting of numbers or letters and numbers, assigned to a product by a retailer for purposes of identification and inventory control.
SMS	Short Message Service. A feature that allows users of a wireless device on a wireless network to receive or transmit short electronic alphanumeric messages (up to 160 characters, depending on the service provider).
S/N	Signal-to-noise (ratio)
SNR	Signal-to-Noise Ratio
SOF	Start of Frame—A USB function.
SSS	Secondary synchronisation signal.
SUPL	Secure User Plane Location
TIA/EIA	Telecommunications Industry Association / Electronics Industry Association. A standards setting trade organization, whose members provide communications and information technology products, systems, distribution services and professional services in the United States and around the world. Consult www.tiaonline.org.
TIS	Total Isotropic Sensitivity

Table F-1: Acronyms and definitions (Continued)

Acronym or term	Definition
TRP	Total Radiated Power
UDK	Universal Development Kit (for PCI Express Mini Cards)
UE	User Equipment
UICC	Universal Integrated Circuit Card (Also referred to as a SIM card.)
UL	Uplink (mobile to network)
UL	Underwriters Laboratory
UMTS	Universal Mobile Telecommunications System
USB	Universal Serial Bus
USIM	Universal Subscriber Identity Module (UMTS)
VCC	Supply voltage (3.3 V)
VSWR	Voltage Standing Wave Ratio
WAN	Wide Area Network
WCDMA	Wideband Code Division Multiple Access (also referred to as UMTS)
WLAN	Wireless Local Area Network
ZIF	Zero Insertion Force



C **Numerics** cable loss overview, 20 antenna, maximum, 37 1xEV-DO CAIT support, 51 overview, 19 capacitors 3D gain, average with SIM, 32 with XIM_DATA / XIM_CLK, 32 gain 3D average (GPS), 67 carrier/operator testing, 81 3GPP compliance CDMA LTE, 21 bands supported, 15 overview, 19 Α frequency band support, 42 TIA/EIA/IS compliance, 21 acceptance tests, 71 cell selection, 16 accessories, 17 certification tests, 72 accuracy (GPS), 43 checklist, design, 69 acquisition time (GPS), 43 communications, host to modem acronyms and definitions, 89-94 design checklist, 70 antenna conducted Tx power tolerances, 43 connection considerations, 37 connection connectors, 23 grounding, 39 custom, design, 38 connectors, 37 diversity antenna, disabling, 38 connectors, required GPS, specifications, recommended, 67 host-module, 18 limit, matching coaxial connections, 37 control interface, 33 location, considerations, 38 CQI, 16 matching, considerations, 38 maximum cable loss, 37 routing, 38 D specification, 65-68 specifications, recommended, 65 DC power consumption averaged call mode LTE / WCDMA / HSPA / testing, 67 HSPA+, 46 antennas design checklist, 69 averaged standby, 45 CDMA, 46 application interface features, 15 approvals, regulatory and industry, 59 desense. See RF AT commands, 82 design checklist averaged call mode LTE / WCDMA / HSPA / HSPA+ DC antennas, 69 power consumption, 46 component placement, 69 averaged standby DC power consumption, 45 EMI/ESD, 69 host/modem communications, 70 power, 69 В thermal, 70 detach procedure, 16 bands supported, RF Development Kit contents, 17 summary, 15 digital interface, 35 CDMA, 42 dimensioned view, 54 LTE, 42 dimensions, 53, 54 bearers, dedicated, 16 Direct IP interface, 51 block diagram diversity antenna

expanded RF, 25

system, 24

bottom view, 54

disabling, 38

drop specifications, 53

diversity connector, location, 37

E	humidity specifications, 53
EDGE	I
connector, required, 18	1
electrical specifications, 23	I/O connector location, 37
electrostatic discharge specifications, 53	I/O rise time requirements, 32
electrostatic discharge. See ESD	impedance
envelope correlation coefficient, 66	module-antenna, 38
environmental specifications, 53–55 ESD	SIM, 32 industry approvals, 59
design checklist, 69 protection requirements, 55	Industry Canada approval, 59
ESD specifications, 53	integration requirements, 18
EVDO	interface
overview, 19	control interface, 33
expanded RF block diagram, 25	digital interface, 35
	Direct IP, 51
_	feature summary, 15
F	host, pin assignments, 25
500	QMI, 51
FCC approval, 59	SIM, 30
FER (Frame Error Rate), 41	software, 51
field of view, 67	USB, 29 interference
filtering, RF desense, 40	
form factor, 53	device generated, 40
FOV, 67	host-generated, 40 power supply noise, 50
frame error rate (FER)	wireless devices, 39
measure of sensitivity, 41 free space average gain, 67	Interoperability testing, 81
frequencies supported, 41	intra-LTE mobility, 16
	IOT testing, 81
frequency band support CDMA, 42	iRAT, 16
LTE, 42	IS-95A
112, 42	overview, 20
C	isolation, 66, 67
G	
gain	L
GPS, 67	
maximum, 60, 66	labeling, 55
mean effective, 66	LED
mean effective imbalance, 66	example, 34
GCF-CC approval, 59	states, 34
General purpose IO (GPIO), 35	LED output, 23, 33, 34
GLONASS, 17	LTE
GPIO (General purpose IO), 35	3GPP compliance, 21
GPS	overview, 19
antenna specifications, recommended, 67	bands supported, 15
connector location, 37	bandwidth support, 42 features, 16
DC bias on connector, 17	frequency band support, 42
features supported, 17	frequency barid support, 42
specifications, 43	
ground specifications, 29	M
grounding connection considerations, 39	
connection considerations, 33	mean effective gain, 66
	mean effective gain imbalance, 66
Н	mechanical specifications, 53-55
	MIB, 16
host interface	MIMO support, 15
pin assignments, 25	

minicom downloading and installing 76	Q
downloading and installing, 76 module	QMI interface, 51
power states, 47–49	QPST (QUALCOMM Product Support Tool), 5 QUALCOMM Product Support Tool (QPST), 5
N	quality assurance tests, 80 QXDM support, 51
NAS/AS security, 16	
NDIS NIC interface support, 15	R
NIC interface support, 15	
noise	radiated efficiency, total, 65
leakage, minimizing, 39	radiated sensitivity measurement, 41
RF interference, power supply, 50	radiated spurious emissions, 40
	radiation patterns, 65
0	references, 87–88
	regulatory approvals, 59
OEM	regulatory information, 59–63
assistance with testing, 81	FCC, 60
labeling, 55	limitation of liability, 59 safety and hazards, 59
operator/carrier testing, 81	resistors, external pull-up, 32
ordering information, 18	RF
	antenna cable loss, maximum, 37
P	antenna connection, considerations, 37
	connectors, required, 18
packaging, 85	desense
packet mode features, 16	device-generated, 40
paging procedures, 16	harmonic energy, filtering, 40
PCB	mitigation suggestions, 40
multi-layer, shielding for RF desense, 40	shielding suggestions, 40
PDN connections, multiple, 16	interference
pin assignments, host interface, 25	other devices, 40
PMI, 16	power supply, 50
polarization, 67 position location, 17	wireless devices, 39
power position location, 17	RF bands supported
design checklist, 69	summary, 15 CDMA, 42
handling, 66	LTE, 42
power-up timing, 49	RF block diagram, expanded, 25
ramp-up timing, 49	RF connector location, 37
state machines, 48	RF specifications, 37–44
states, module, 47-49	RI, 16
supply, RF interference, 50	RSE, 40
supply, ripple limit, 50	Rx sensitivity
power consumption, DC	conducted, 42
averaged call mode LTE / WCDMA / HSPA / HSPA+, 46	
averaged standby, 45	S
CDMA, 46	•
power specifications, 29	sales
power tolerances, conducted Tx, 43 Product Support Tool, QUALCOMM (QPST), 51	ordering, 18
Product Support Tool, GOALCOMM (GFST), 51 Product Support Tool, Sierra Wireless (PST), 51	SED
production tests, 73	see Smart Error Detection
PSS, 16	See also W_DISABLE_N, 33
PST (Product Support Tool, Sierra Wireless), 51	sensitivity
PTCRB approval, 59	conducted, RF parameter, 42
	defined, 41
	radiated measurement, overview, 41 testing, overview, 41

```
shielding
                                                                     thermal
     module, compliance, 37
                                                                          considerations, 56-57
     reducing RF desense, 40
                                                                          design checklist, 70
shock specifications, 53
                                                                          dissipation, factors affecting, 56
SIB, 16
                                                                          dissipation, suggestions, 56
                                                                          RF shield temperature, maximum, 57
signals, 33
    WLAN_LED_N, 34
                                                                          testing, module, 57
SIM
                                                                     TIA/EIA/IS compliance
     capacitor recommendations, 32
                                                                          CDMA, 21
     card contacts, 31
                                                                     timing
     clock rate, 32
                                                                          power ramp-up, 49
     connector, required, 18
                                                                          power-up, 49
     electrical specifications, 32
                                                                     top view, 54
     impedance, connectors, 32
                                                                     Tx power tolerances, conducted, 43
     interface, 30
    interface diagram, 31
                                                                     U
    operation, 32
Smart Error Detection
                                                                     UDK, 17
    detecting module reset, 50
                                                                     Universal Development Kit, 17
SMS features, 16
                                                                     USB
Snow 3G/AES security, 16
                                                                          drivers, user-developed, 30
software interface, 51
                                                                          enumeration, power-up, 49
specifications
                                                                          high / full speed throughput performance, 29
     electrical, 23
                                                                          interface, 29
     environmental specifications, 53-55
     GPS, 43
     mechanical, 53-55
                                                                     V
     RF, 37-44
SSS, 16
                                                                     vibration specifications, 53
                                                                     VSWR, 65, 67
standalone mode, GPS, 17
standby DC power consumption, averaged, 45
state machines, 48
                                                                     W
support
     features, 17
                                                                     W_DISABLE_N, 33
     testing assistance by Sierra Wireless, 81
                                                                     warranty, 17
     tools, 51
                                                                     Wireless Disable, 23, 33
system acquisition, 16
                                                                     Wireless Disable (Main RF), 33
system block diagram, 24
                                                                     WLAN_LED_N, 33, 34
                                                                     WMC DLL support, 16
Т
                                                                     Ζ
temperature specifications, 53
temperature, module. See thermal
                                                                     ZIF (Zero Intermediate Frequency), 39
testing
     overview, 71
     acceptance tests, 71
     assistance provided by Sierra Wireless, 81
     certification tests, 72
     equipment, suggested, 81
     interoperability and operator/carrier testing, 81
     manual functional test, suggested, 73
     production tests, 73
     quality assurance tests, 80
     RF receive path, CDMA, 77
     RF receive path, LTE, 78
     suggestions, 71-84
```

